

Project Name: PIBTDL/LC AIO
Project Code: 3PD01Z010001
PCB Number : 14060
PCB Size : 150mmx200mm
PCB Name : LC AIO_Intel BT MB

PAGE	TITLE	NOTE	PAGE	TITLE	NOTE
01	Cover Page		32	HDD/ODD	
02	Block Diagram		33	USB 2.0 Power SW	
03	Power Delivery		34	USB 3.0 Port	
04	Power Sequence		35	USB HUB IC	
05	Power Good & Reset Diagram		36	Rear USB/TOU/WEBCAM	
06	Clock Map		37	MINI PCIE CARD (WLAN / BT)	
07	GPIO Table		38	SIO-ITE8772E-EX	
08	Audio Block Diagram		39	SIO-ITE8732	
09	CPU (DDR)(1/11)		40	RTD2136 eDP to LVDS	
10	CPU (VCC CORE)(2/11)		41	PWRBIN/SIDE KEY/LED	
11	CPU (DDI/EDP/GPIO)(3/11)		42	XDP	
12	CPU (USB/LPC/GPIO)(4/11)		43	(Reserved) SCALAR POWER	
13	CPU (CLK/SPI/SIDEBAND/JTAG) (5/11)		44	STAND OFF/HOLE/EMI CAP	
14	CPU (SATA/PCIE/IHDA) (6/11)		45	HeatSink/Battery/etc	
15	CPU (POWER) (7/11)		46	(Reserved) GPU:PEC Express (1/5)	
16	CPU (POWER CAP1) (8/11)		47	(Reserved) GPU:IFB(IO) (2/5)	
17	CPU (POWER CAP2) (9/11)		48	(Reserved) GPU:MEMROY FBA (3/5)	
18	CPU (VSS) (10/11)		49	(Reserved) GPU:GPIO/STRAP (4/5)	
19	CPU (STRAP) (11/11)		50	(Reserved) GPU:PWR/GND (5/5)	
20	(Reserved) DDR3L-SODIMM1		51	(Reserved) GPU DDR3 128MX16	
21	DDR3L-SODIMM2		52	(Reserved) GPU POWER Sequence	
22	(Reserved) Front BD Connector		53	(Reserved) GPU_CTF/PPLAY/LDO/MVDD	
23	AUDIO CODEC-ALC269Q		54	(Reserved) GPU VDDC_NCP81172	
24	Combo Jack & Speaker		55	PWR DCIN JACK	
25	LAN RTL8111GA		56	PWR_CPU CORE&VNN	
26	RTS5170 (CARD READER)		57	PWR_5V/3D3V	
27	RUN POWER & SEQUENCE		58	PWR_1D8V_S5	
28	(Reserved) Aspire Link		59	PWR_1D35V_OD675_TPS51363	
29	LCD CONN/CVR		60	PWR_CPU_1V_S0&CPU_1V_S5	
30	HDMI OUT		61	PWR_1P5_S0&1P05_S0&1P8V_S0	
31	(Reserved) HDMI IN		62	PWR_12V	

KC.BTD01.29C : Bay Trail-D PENTIUM J2900 4C 2.4G C0
KC.BTD01.19C : Bay Trail-D CELERON J1900 4C 2.0G C0
KC.BTD01.18C : Bay Trail-D CELERON J1800 2C 2.4G C0
KC.29301.BMC : Bay Trail-M CELERON N2930 1.86G

071.00BAY.0C6U : Bay Trail-D PENTIUM J2900 4C 2.4G C0
071.00BAY.0C4U : Bay Trail-D CELERON J1900 4C 2.0G C0
071.00BAY.0C5U : Bay Trail-D CELERON J1800 2C 2.4G C0

XTAL Description

XTAL	Function	Frequency	Spec	Capacitance
X1801	CPU	25M	+/-30ppm CL:12P	C1814=12pF C1815=12pF
X1802	CPU	32.768K	+/-20ppm CL:7P	C1817=4pF C1818=4pF
X3	LAN	25M	+/-30ppm CL:12P	C294=15pF C295=15pF
X3501	HUB	12M	+/-20ppm CL:20P	C4603=18pF C4604=18pF
X5	SCALAR	14.318M	+/-20ppm CL:20P	C532=15pF C533=15pF
X7	GPU	27M	+/-30ppm CL:12P	C738=10pF C734=10pF

BOM Configuration

O_ : OCP
O6_ : 65W adaptor
O9_ : 90W adaptor
R_ : Reserve
ECIO_ : ITE8732
SIO_ : ITE8772
L18_ : 18 inch Panel
L19_ : 19.5 inch Panel
CMI_ : CHIMEI Panel
ODT_ : ODT Panel

CPU: INTEL BAY TRAIL-D
J2900 - KC.BTD01.29C
J1900 - KC.BTD01.19C
J1800 - KC.BTD01.18C

SIO: IT8732F
BX - 71.08732.00E
CX - 71.08732.A0E
SCALAR: RTD2486
71.02486.D0G
LAN: RTL8111GA
71.08111.Y03
Audio Codec: ALC269Q
71.00269.H03
Amplifier: TAS5707
74.05707.01T
USB3.0 redriver: PS8713
71.08713.003
SATA3.0 redriver: PS8520
71.08520.003
LVDS translator: RTD2136
71.02136.B04

CMI 19.5"
1.L19_
2.SIO_
3.O_
4.O6_
5.CMI_

ODT 18.5"
1.L18_
2.SIO_
3.O_
4.O6_
5.ODT_

<Variant Name>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title

Cover Page

Size

Document Number

Low Cost AIO

Rev

TA

Date

Friday, September 12, 2014

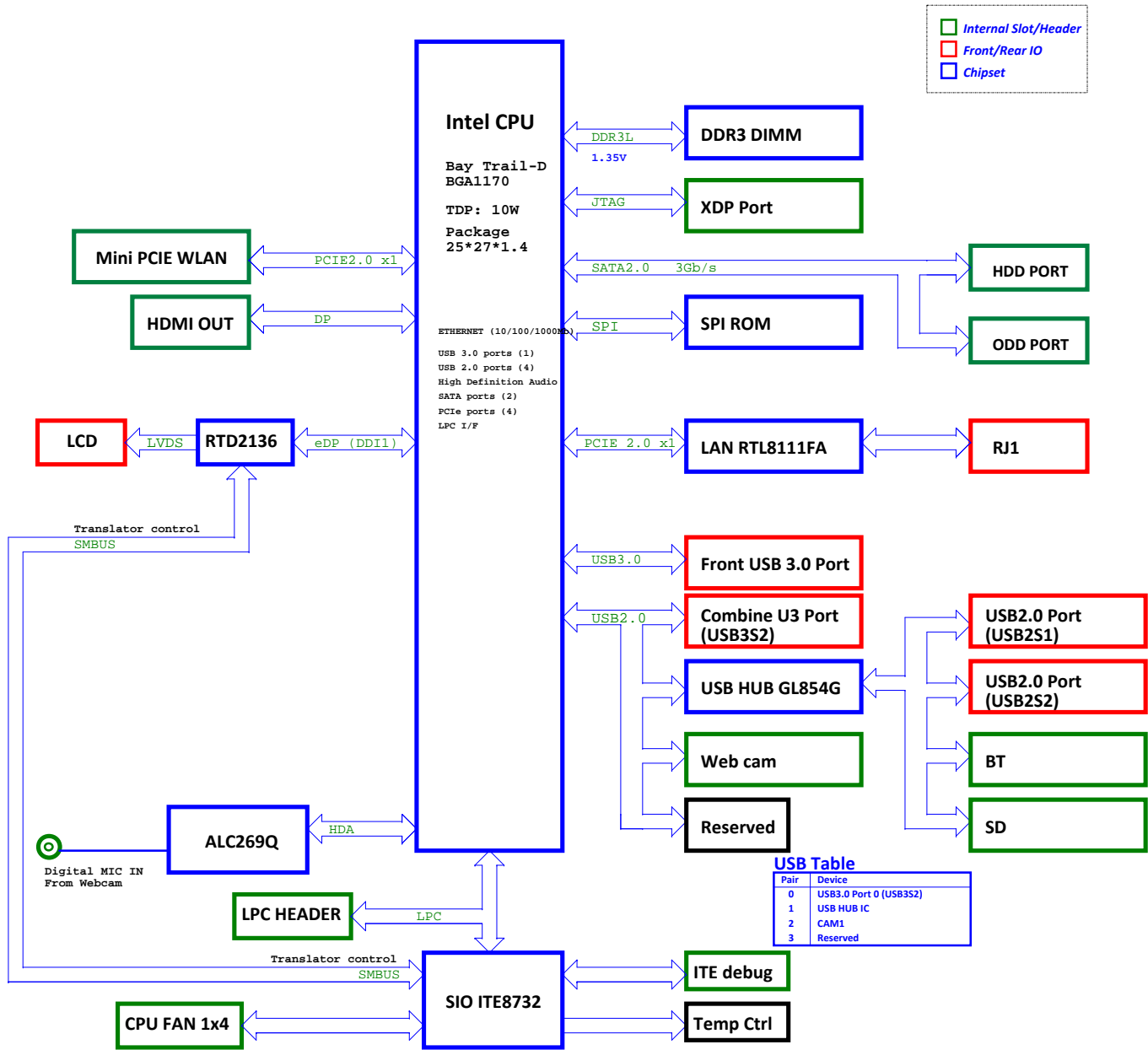
Sheet

1

of

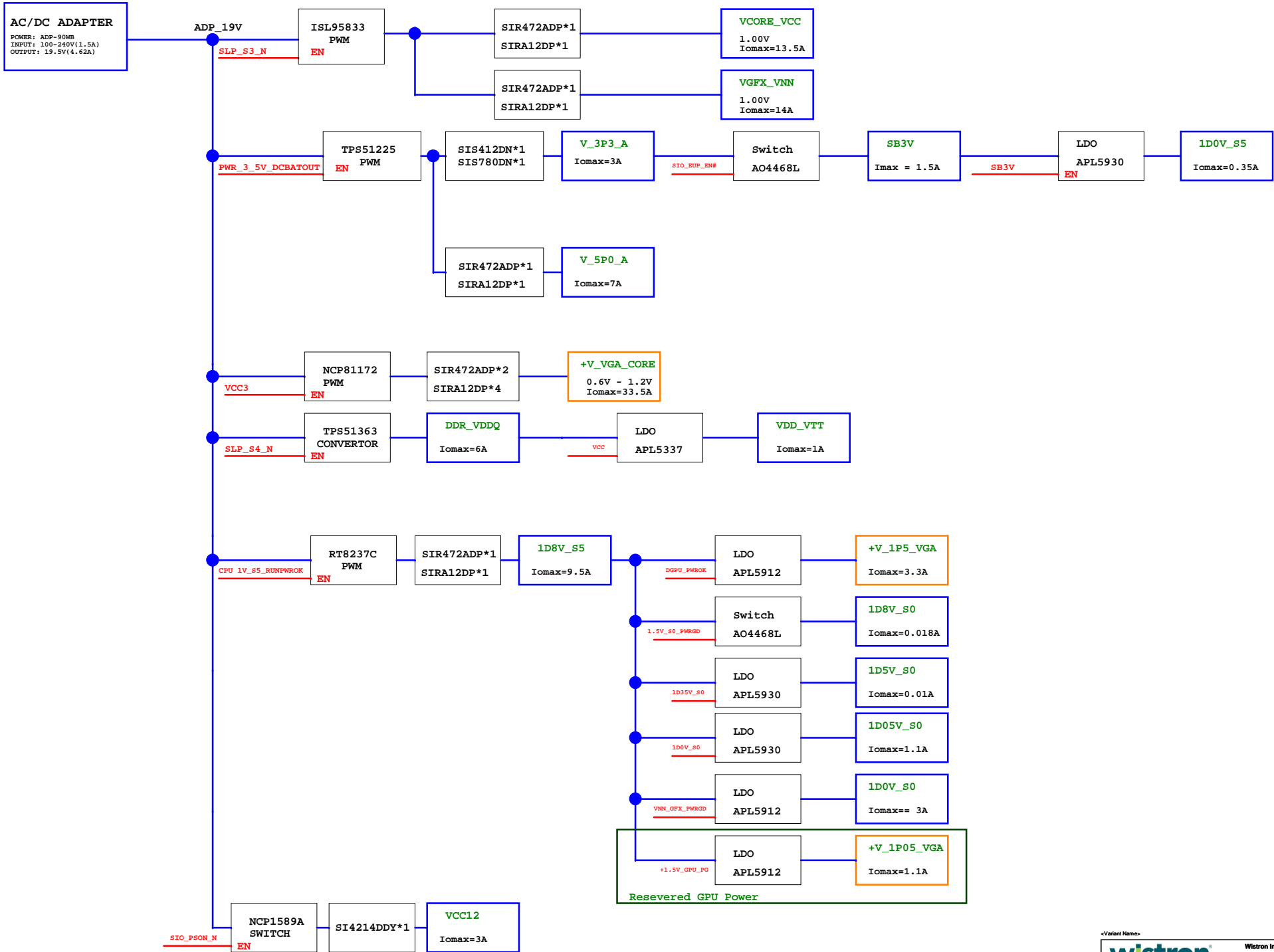
62

Project Name: PIBTDL/LC AIO
Project Code: 3PD01Z010001
PCB Number : 14060
PCB Size : 150mmx200mm
PCB Name : LC AIO_Intel BT MB

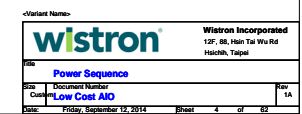


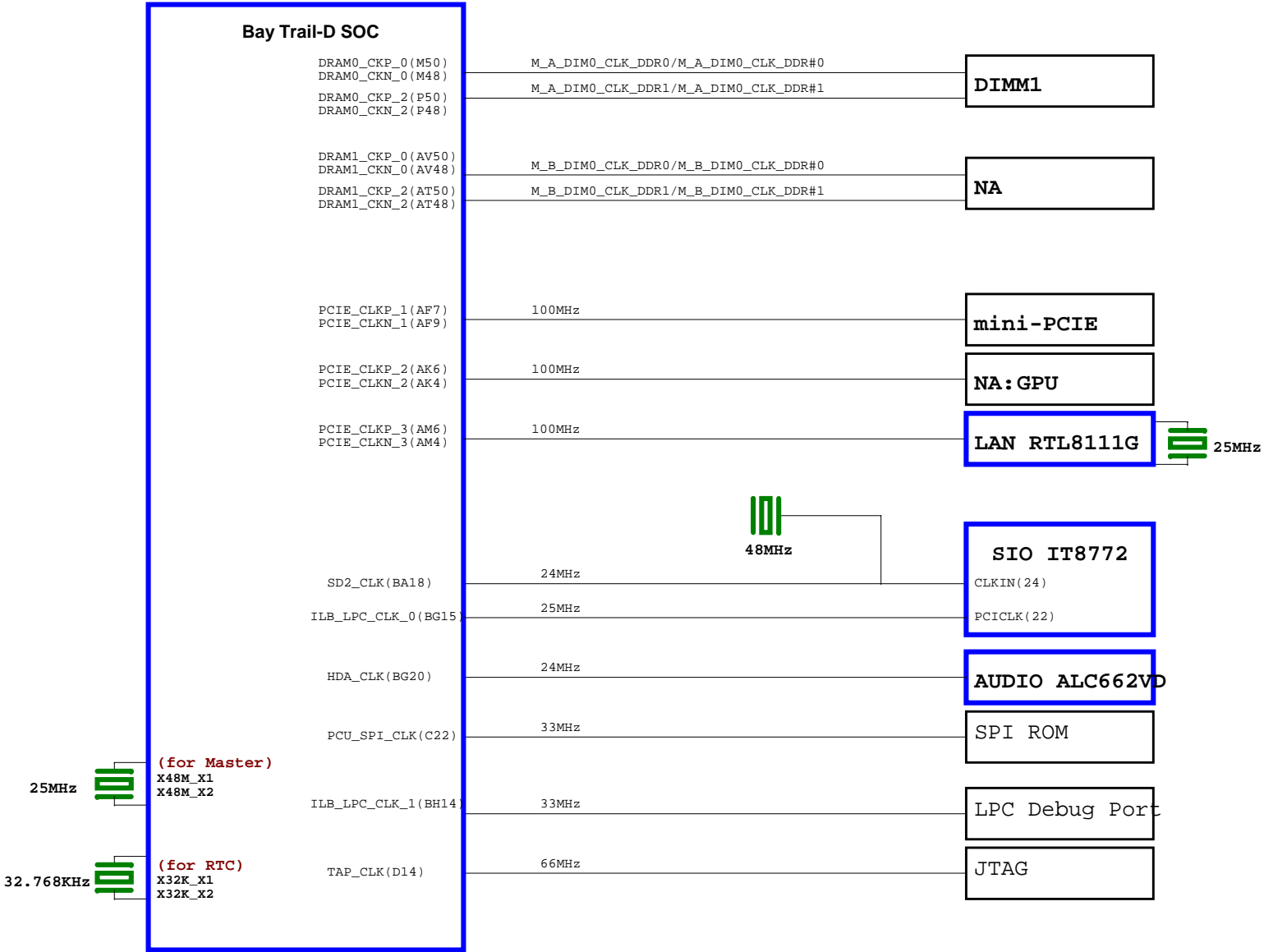
USB Table

Pair	Device
0	USB3.0 Port 0 (USB3S2)
1	USB HUB IC
2	CAM1
3	Reserved



Source	Destination	Signal
--------	-------------	--------





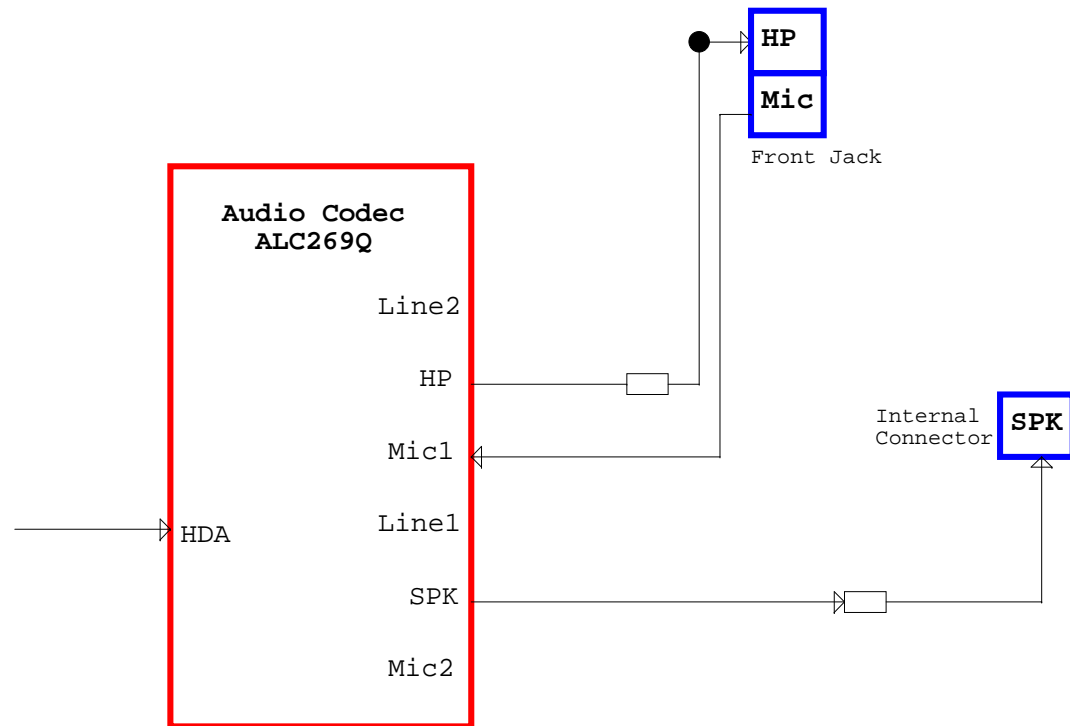
Vinafix

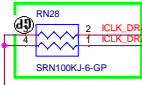
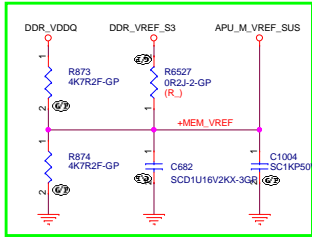
Dallas GPIO Table

Version: 2012/11/27

IC Pin Name	Power Well	Default	Default State	Signal Name	Usage	BIOS Programming					Comment
						S0	S1	S3	S4	S5	
GENINT1_L/GPIO32	VDD_33	null	Input, 15K PU	no use	no use						
GENINT2_L/GPIO33	VDD_33	null	Input, 15K PU	no use	no use						
SCLO/GPIO43	VDD_33	null	Input	SMBUS_CLK	SMBUS0	Native	Native	Native	Native	Native	2.2K to 3D3V_S0
SD_LED/GPIO45	VDD_33	null	Output	no use	no use						
SDAQ/GPIO47	VDD_33	null	Input	SMBUS_DATA	SMBUS0	Native	Native	Native	Native	Native	2.2K to 3D3V_S0
SERIRQ/GPIO48	VDD_33	SERIRQ	Input, 15K PU	SERIRQ_N	SERIRQ	Native	Native	Native	Native	Native	10k(R) to 3D3V_S0
GPIO49	VDD_33	GPIO49	Input	no use	no use						
GPIO50	VDD_33	GPIO50	Input, 15K PU	KEY0_TEST	BTN test	GPI	GPI	GPI	GPI	GPI	1K to 3D3V_S0
GPIO51	VDD_33	GPIO51	Input	TP51	no use						
FANOUT0/GPIO52	VDD_33	null	Output, 15K PU	no use	no use						
DEVSLP[0]/GPIO55	VDD_33	GPIO55	Input, 15K PU	TP29	no use						
FANIN0/GPIO56	VDD_33	null	Input, 15K PU	no use	no use						
GPIO57	VDD_33	GPIO57	Input, 15K PU	TP48	no use						
GPIO58	VDD_33	GPIO58	Input, 15K PU	TP49	no use						
DEVSLP[1]/GPIO59	VDD_33	GPIO59	Input, 15K PU	PANEL_OFF_R	panel ON/OFF	GPI	GPI	GPI	GPI	GPI	EC: 10k to 3D3V_A scalar: 10k to P3P3V
CLK_REQ0_L/ SATA_ISO_L/ SATA_ZP0_L/GPIO60	VDD_33	null	Input, 15K PU	BLANCLK_REQ_N_1	clock request (Reserved)						10k(R) to 3D3V_S0
CLK_REQ1_L/GPIO61	VDD_33	null	Input, 15K PU	CLK_PCIE_WLAN_REQ#	clock request (Reserved)						
CLK_REQ2_L/GPIO62	VDD_33	null	Input, 15K PU	no use	no use						
CLK_REQ3_L/ SATA_IS1_L/ SATA_ZP1_L/GPIO63	VDD_33	null	Input, 15K PU	no use	no use						
GPIO64	VDD_33	GPIO64	Input, 15K PU	SMBUS_SSP	scalar FW	GPO L	GPO L	GPO L	GPO L	GPO L	100k to GND controlled by SW tool
CLK_REQ0_L/GPIO65/ OSCIN	VDD_33	null	Input, 15K PU	PEG_CLKREQ#	clock request (Reserved)						
SPKR/GPIO66	VDD_33	SPKR	Output	SPKR	beep	Native	Native	Native	Native	Native	
SATA_ACT_L/GPIO67	VDD_33	SATA_ACT_L	Output	no use	no use						
GPIO68	VDD_33	GPIO68	Input, 15K PU	SYS_ID2	SYS ID	GPI	GPI	GPI	GPI	GPI	
GPIO69	VDD_33	GPIO69	Input, 15K PU	SYS_ID3	SYS ID	GPI	GPI	GPI	GPI	GPI	
GPIO70	VDD_33	GPIO70	Input, 15K PU	APU_PROCHOT#_R	thermal (Reserved)						1K to 3D3V_S0
GPIO71	VDD_33	GPIO71	Input	SYS_ID1	SYS ID	GPI	GPI	GPI	GPI	GPI	
SD_CLK/SCUK_2/ GPIO73	VDD_33	null	Input, 50K PU	no use	no use						
SD_CMD/GPIO74	VDD_33	null	Input, 50K PU	no use	no use						
SD_CD/GPIO75	VDD_33	null	Input, 50K PU	no use	no use						
SD_WP/GPIO76	VDD_33	null	Input, 50K PU	no use	no use						
SD_DATA0/SDAT1_2/ GPIO77	VDD_33	null	Input, 50K PU	no use	no use						
SD_DATA1/SDAT0_2/ GPIO78	VDD_33	null	Input, 50K PU	no use	no use						
SD_DATA2/GPIO79	VDD_33	null	Input, 50K PU	no use	no use						
SD_DATA3/GPIO80	VDD_33	null	Input, 50K PU	no use	no use						
SPI_WP_L/GPIO161	VDD_33_ALW	SPI_WP_L	Input	ROM_RST#	SPI	Native	Native	Native	Native	Native	10k to 3D3V_S5
SPI_CLK/GPIO162	VDD_33	SPI_CLK	Input, 15K PD	SPI_CLK	SPI	Native	Native	Native	Native	Native	
SPI_DO/GPIO163	VDD_33_ALW	SPI_DO	Input, 15K PD	SPI_DATAOUT	SPI	Native	Native	Native	Native	Native	
SPI_DI/GPIO164	VDD_33_ALW	SPI_DI	Input, 15K PD	SPI_DATAIN	SPI	Native	Native	Native	Native	Native	
SPI_CS1_L/GPIO165	VDD_33	SPI_CS1_L	Input, 15K PU	SPI_CS0_N	SPI	Native	Native	Native	Native	Native	10k to 3D3V_S5
SPI_CS2_L/GPIO166	VDD_33	SPI_CS2_L	Input, 15K PU	EDID_RDY	EDID for APU	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_S5
AZ_S0IN0/GPIO167	VDD_33_ALW	AZ	Input, 13.6K PD	AZ_S0IN0	AZ	Native	Native	Native	Native	Native	10k(R) to GND
AZ_S0IN1/GPIO168	VDD_33_ALW	AZ	Input, 13.6K PD	AZ_S0IN1	AZ	Native	Native	Native	Native	Native	10k(R) to GND
AZ_S0IN2/GPIO169	VDD_33_ALW	AZ	Input, 13.6K PD	AZ_S0IN2	AZ	Native	Native	Native	Native	Native	10k(R) to GND
AZ_S0IN3/GPIO170	VDD_33_ALW	AZ	Input, 13.6K PD	AZ_S0IN3	AZ	Native	Native	Native	Native	Native	10k(R) to GND
GPIO174	VDD_33_ALW	GPIO 174	Input	Wake#_PCIE	wake up	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_S5
IR_LED_L/LB_L/GPIO184	VDD_33_ALW	null	Input, 15K PU	Wake#_LOM	wake up	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_S5
SC11/GPIO227	VDD_33_ALW	null	Input	SMB1_CLK	SMBUS1	Native	Native	Native	Native	Native	2.2K to 3D3V_S5
SDA1/GPIO228	VDD_33_ALW	null	Input	SMB1_DATA	SMBUS1	Native	Native	Native	Native	Native	2.2K to 3D3V_S5
GA20IN/GEVENT0#	VDD_33	GA20 IN	Input, 15K PU	KA20GATE	GA20IN	Native	Native	Native	Native	Native	10k(R) to 3D3V_S0
GEVENT2#	VDD_33_ALW	null	Input, 15K PU	SPI_SW	only strapping						strap low
LPC_PME#/ GEVENT3#	VDD_33_ALW	null	Input, 15K PU	PME#_M	LPC	Native	Native	Native	Native	Native	2.2k(R) to 3D3V_S5
GEVENT4#	VDD_33_ALW	null	Input	THERMAL_SHUT#	thermal (Reserved)						10k(R) to 3D3V_S5
LPC_PDR/ GEVENT5#	VDD_33_ALW	null	Output	TP_LPC_PDR#	no use						
IR_TX1/ GEVENT6#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
GEVENT7#	VDD_33_ALW	null	Input	EC_SMI#	(Reserved)						10k to 3D3V_S5
WAKE#/ GEVENT8#	VDD_33_ALW	null	Input, 15K PU	PCIE_WAKE#	wake up	Native	Native	Native	Native	Native	10k to 3D3V_S5
SPI_HOLD#/ GEVENT9#	VDD_33_ALW	Strap	Input	SST_HOLD#_1_R	SPI	Native	Native	Native	Native	Native	10k to 3D3V_S5
GEVENT10#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
GEVENT11#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
USB_OC0#/SPI_TPM_CS#/ TRST#/ GEVENT12#	VDD_33_ALW	USB_OC0#	Input, 15K PU	USB_OC_01	USB OCP	Native	Native	Native	Native	Native	10k to 3D3V_S5
USB_OC1#/TDI/ GEVENT13#	VDD_33_ALW	no use	Input, 15K PU	USB_OC_23	USB OCP	Native	Native	Native	Native	Native	10k to 3D3V_S5
USB_OC2#/TCK/ GEVENT14#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
USB_OC3#/TDO/ GEVENT15#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
AC_PRES#/IR_RX0/ GEVENT16#	VDD_33_ALW	null	Input, 15K PU	AC_PRES	no use						
GEVENT17#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
BLINK/ GEVENT18#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
SYS_RESET#/ GEVENT19#	VDD_33_ALW	SYS_RESET_L	Input, 15K PU	FP_RST_N	no use						
IR_RX1/ GEVENT20#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
IR_TX0/ GEVENT21#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
GEVENT22#	VDD_33_ALW	null	Input, 15K PU	no use	no use						
LPC_SMI#/ GEVENT23#	VDD_33_ALW	null	Input, 15K PU	no use	no use						

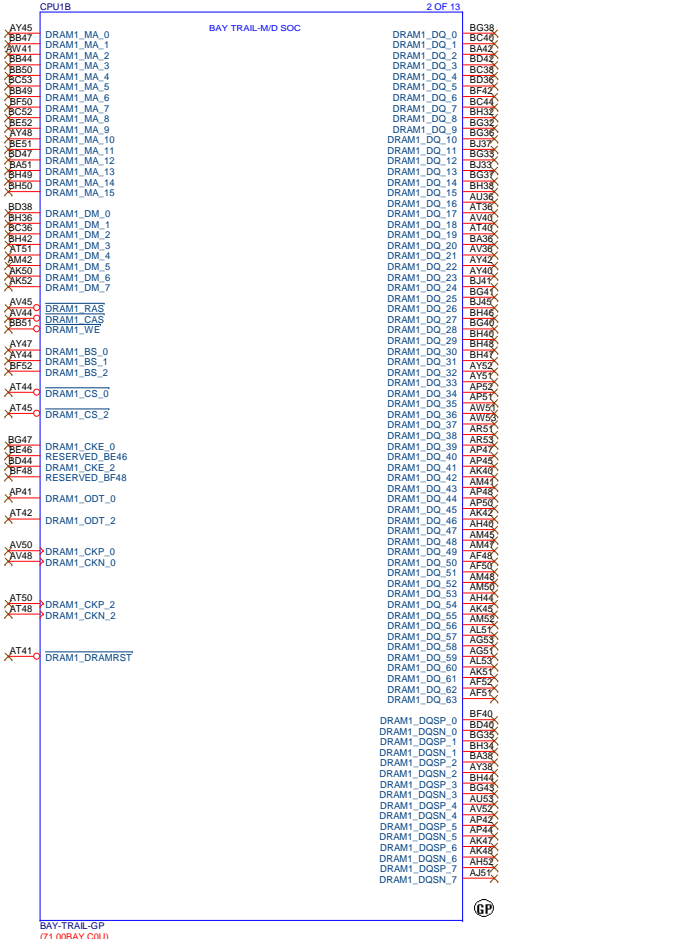
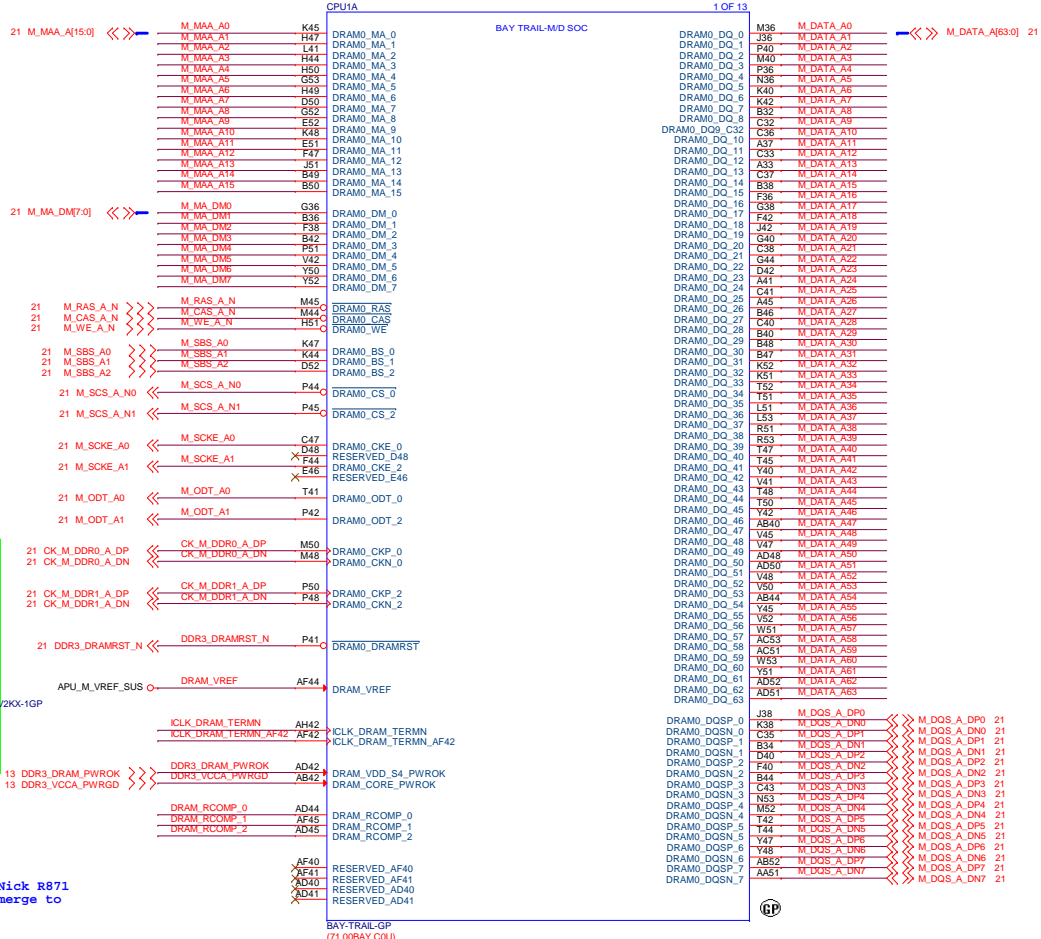
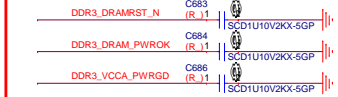
IC Pin Name	Power Well (GPIO)	Default	Default State	Signal Name	Usage	Open Drain / Push Pull	BIOS Programming					Comment
							S0	S1	S3	S4	S5	
PCIRST3#/GP10	3V58	PCIRST3#	Native	AMP_PDN#	mute	DO/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A controlled by EC H: ON, L: OFF/mute
PCIRST2#/GP11	3V58	PCIRST2#	Native	PCIRST2#	RESET	DO/DI/O	Native	Native	Native	Native	Native	10k(R) to 3D3V_A
PCIRST1#/GP12	3V58	PCIRST1#	Native	PCIRST1#	RESET	DO/DI/O	Native	Native	Native	Native	Native	10k(R) to 3D3V_A
PWROK1/GP13	3V58	PWROK1	Native	PWROK3_1	PWROK	DO/DI/O	Native	Native	Native	Native	Native	1k to 3D3V_S0 set delay to 200ms
VCORE_EN/PCN_C1/GP14	3V58	VCORE_EN	Native	LAN_PWR_EN	LAN power (reserved)	DO/DI/O/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	390k to 3D3V_S5
PCIRST1#N/CIRTX2/GP15/CPU_PG	3V58	CIRTX2	Native	SIO_PCIRST1#N	RESET	D/DI/O/DI/O/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A
SVS8_CTRL#/ CIRRX2/GP16	3V58	SVS8_CTRL#	Native	EC_EUP	EUP	DO/DI/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A
RI2H/GP17	3V58			SPI_WP_R_N	SPI WP	DI/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A H: can write L: write protect
CTS2H/GP20	3V58	GP20		PANEL_SW_EC	panel ON/OFF	DI/DI/O	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_A controlled by EC
DCD2H/GP21	3V58	GP21		PANEL_CTRL	panel ctrl (reserved)	DI/DI/O	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_A controlled by EC
SKC/GP22	3V58	GP22		SIO_SCK_R	EC EPROM	DO/DI/O	Native	Native	Native	Native	Native	1k to 3D3V_A
SI/GP23	3V58	GP23		SIO_SI	EC EPROM	DO/DI/O	Native	Native	Native	Native	Native	1k to 3D3V_A
RTS2H/GP24	3V58	GP24		THERMAL_SHUT#_SIO	thermal (reserved)	DO/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k(R) to 3D3V_S5
DSR2H/GP25	3V58	GP25		SIO_Audio_Mute	mute (reserved)	DI/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A
SOUT2/GP26	3V58	GP26		SIO_UART1_TX	UART	DO/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A
SIN2/GP27	3V58	GP27		SIO_UART1_RX	UART	DI/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A
ATXP/GP30	3V58	ATXP	Native	SIO_ATXP	sequence	DI/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_S0
PWMOUT/GP31	3V58	PWMOUT	Native	W3_DISABLE_N	wake up	DO/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_S5 L: disable
DPWROK/GP32	3V58	DPWROK	Native	W1_DISABLE_N	wake up	DO/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_S5 L: disable
SUSACK#/GP33	3V58	SUSACK#	Native	SIO_BOARD_ID3	board ID	DO/DI/O	GPI	GPI	GPI	GPI	GPI	controlled by EC H: scalar, L: non-scalar
SUSWARN#/GP34	3V58	SUSWARN#	Native	SIO_BOARD_ID2	board ID	DO/DI/O	GPI	GPI	GPI	GPI	GPI	board stage
FAN_TAC4/GP35	3V58	FAN_TAC4	Native	SIO_BOARD_ID1	board ID	DI/DI/O	GPI	GPI	GPI	GPI	GPI	board stage
FANCTL3/GP36	3V58	FANCTL3	Native	no use	no use	DO/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	
FAN_TAC3/GP37	3V58	FAN_TAC3	Native	EC_AMP_RST	mute	DI/DI/O	GPO L	GPO L	GPO L	GPO H	GPO H	10k to 3D3V_A controlled by EC H: reset/mute, L: normal
3V5BSW#/GP40	3V58	3V5BSW#	Native	SLP_S3_N_R3	sequence	DO/DI/O	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_S5 controlled by EC
PWROK2/GP41	3V58	PWROK2	Native	PWROK3_2	PWROK (reserved) S0 power (reserved)	DO/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_S5
PSON#/GP42	3V58	PSON#	Native	SIO_PSON_N		DO/DI/O	Native	Native	Native	Native	Native	4.7k to 3D3V_A
PANSWH#/GP43	3V58	PANSWH#	Native	PB_IN_N_1	PWR BTN	DI/DI/O	Native	Native	Native	Native	Native	330k to 3D3V_A
PWRONH#/GP44	3V58	PWRONH#	Native	SW_ON_N_SIO	sequence	DO/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_S5
D_RX0#/SMCLK2/ GP46	3V58			SMBCLK2_SIO	SIO SMBUS2	DI/DO/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A controlled by EC
D_TOX#/SMDAT2/ GP47	3V58	null		SMBDAT2_SIO	SIO SMBUS2	DO/DI/O/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_A controlled by EC
GP0/GP50	3V58	S0	Native	SIO_S0	EC EPROM	DI/DI/O	Native	Native	Native	Native	Native	1k to 3D3V_A
FANCTL2/GP51	3V58	FANCTL2	Native	SUSLED_R_N	LED	DO/DI/O	Native	Native	Native	Native	Native	10k to USB30_VCCA
FAN_TAC2/GP52	3V58	FAN_TAC2	Native	EC_SMI#	(Reserved)	DI/DI/O	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_S5
SUSCH#/GP53	3V58	SUSCH#	Native	SLP_S5_N_R	sequence	DI/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_S5
PME#/GP54	3V58	PME#	Native	LPC_PME_N	LPC	DO/DI/O	Native	Native	Native	Native	Native	2.2k(R) to 3D3V_S5
RSRMR2#/CIRRX1/GP55	3V58	RSRMR2#	Native	ICH_RSMRST_N_R	sequence	DO/DI/DI/O	Native	Native	Native	Native	Native	10k to 3D3V_S5
MCLK/GP56	3V58	MCLK	Native	MCLK	no use	DI/DO/DI/O	Native	Native	Native	Native	Native	10k to SV_S5
MDAT/GP57	3V58	MDAT	Native	MDAT	no use	DI/DO/DI/O	Native	Native	Native	Native	Native	10k to SV_S5
KCLK/GP60	3V58	KCLK	Native	KBCLK	no use	DI/DO/DI/O	Native	Native	Native	Native	Native	10k to SV_S5
KDAT/GP61	3V58	KDAT	Native	KDAT	no use	DI/DO/DI/O	Native	Native	Native	Native	Native	10k to SV_S5
KRST#/GP62	3V58	KRST#	Native	KBRST_N	KBRST	DO/DI/O	Native	Native	Native	Native	Native	10k(R) to 3D3V_S0
SLP_SUS#/VLDI_EN/GP63	3V58	SLP_SUS#	Native	APU_PROCHOT#	(Reserved)	DI/DO/DI/O	GPI	GPI	GPI	GPI	GPI	1k to 3D3V_S0 controlled by EC
GP70/KSIO	3V58	KSIO	Native	DET_HDMI	scalar/HDMI	DI/O/DI	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_A controlled by EC
GP71/KS11	3V58	KS11	Native	SCALAR_EN	scalar/HDMI	DI/O/DI	GPO H	GPO H	GPO H	GPO L	GPO L	10k to 3D3V_A controlled by EC H: enable scalar
GP72/KS00	3V58	KS00	Native	EUP_DSW_SEL	strap	DI/O/DI	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A
GP73/KS01	3V58	KS01	Native	SIO_PANEL_ON	panel ON/OFF	DI/O/DI	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A controlled by EC L: panel ON
GP74/KS02	3V58	KS02	Native	SIO_PANEL_OFF	panel ON/OFF	DI/O/DI	GPO H	GPO H	GPO H	GPO H	GPO H	10k to 3D3V_A controlled by EC L: panel OFF
GP75/KS03	3V58	KS03	Native	LVDS_BLEN_1	panel ON/OFF	DI/O/DI	GPI	GPI	GPI	GPI	GPI	10k to 3D3V_A controlled by EC
GP76/KS04	3V58	KS04	Native	no use	no use	DI/O/DI	GPO H	GPO H	GPO H	GPO H	GPO H	
GP77/KS05	3V58	KS05	Native	SIO_MEM_EVENT_L	power consum. (reserved)	DI/O/DI	GPO H	GPO H	GPO H	GPO H	GPO H	controlled by EC
IO_SCH#/GP85/SMDATO	3V58			SIO_SMDATO	SIO SMBUS0	DO/DI/O/DI/O	Native	Native	Native	Native	Native	4.7k to 3D3V_S0 controlled by EC
GP86/SMCLK0	3V58			SIO_SMCLK0	SIO SMBUS0	DI/O/DI/O	Native	Native	Native	Native	Native	4.7k to 3D3V_S0 controlled by EC



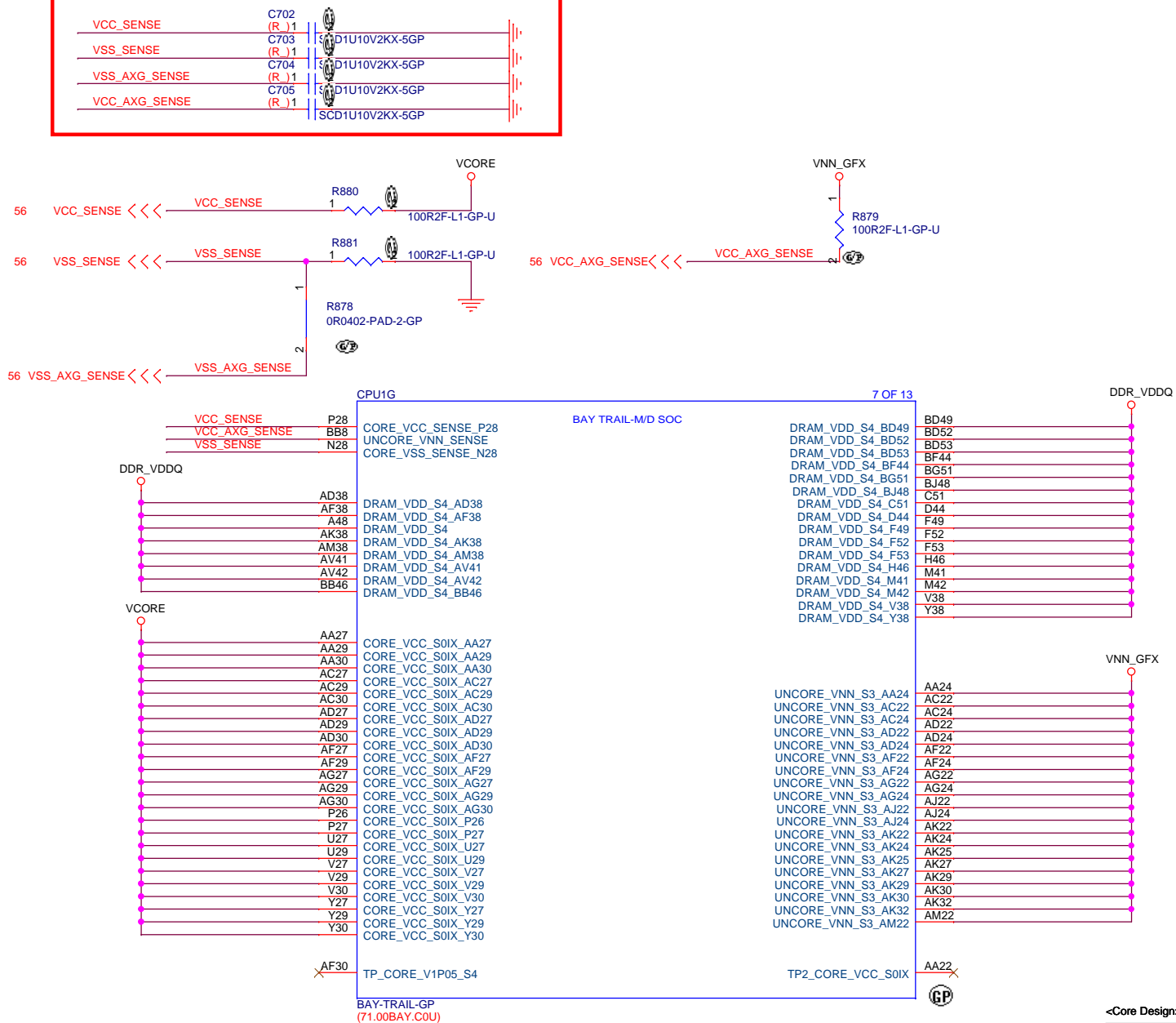


20140509 Nick R871
and R872 merge to
SRN100K

reserve the 0402 0.1u caps on reset for EMI.



reserve the 0402 0.1u caps on reset for EMI



<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title

CPU (VCC CORE)

Size

Document Number

Custom

Low Cost AIO

Rev

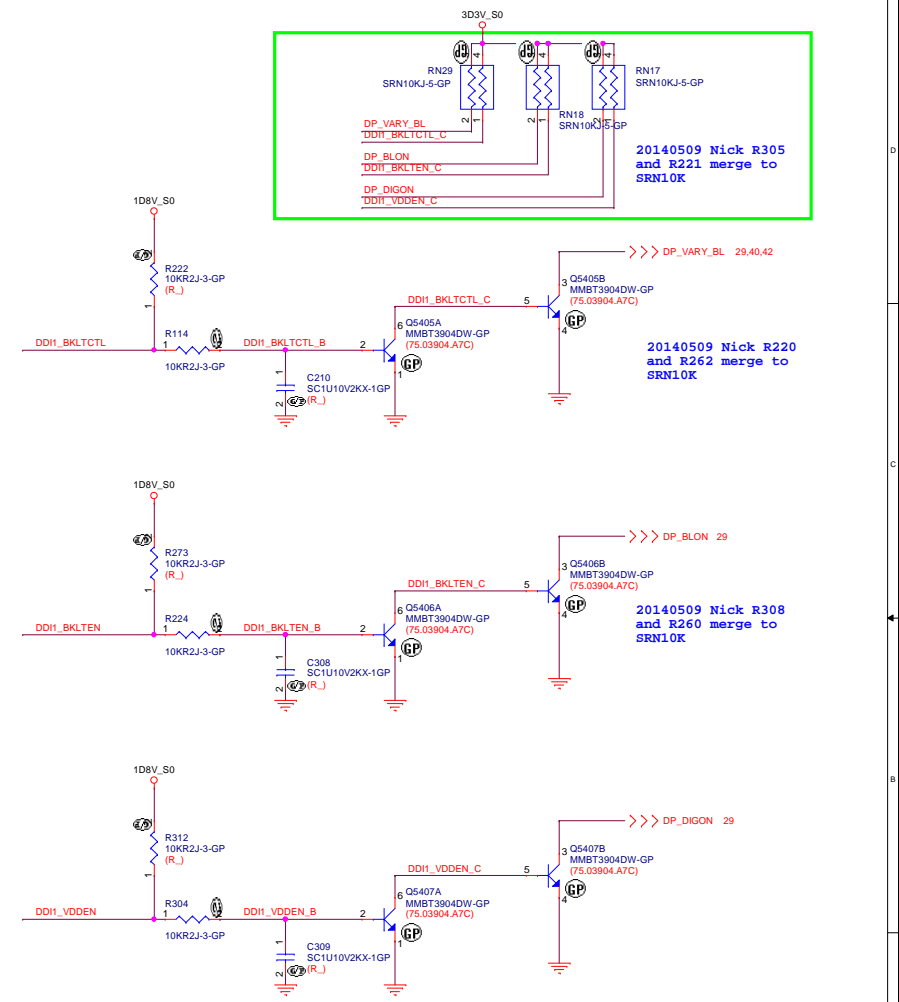
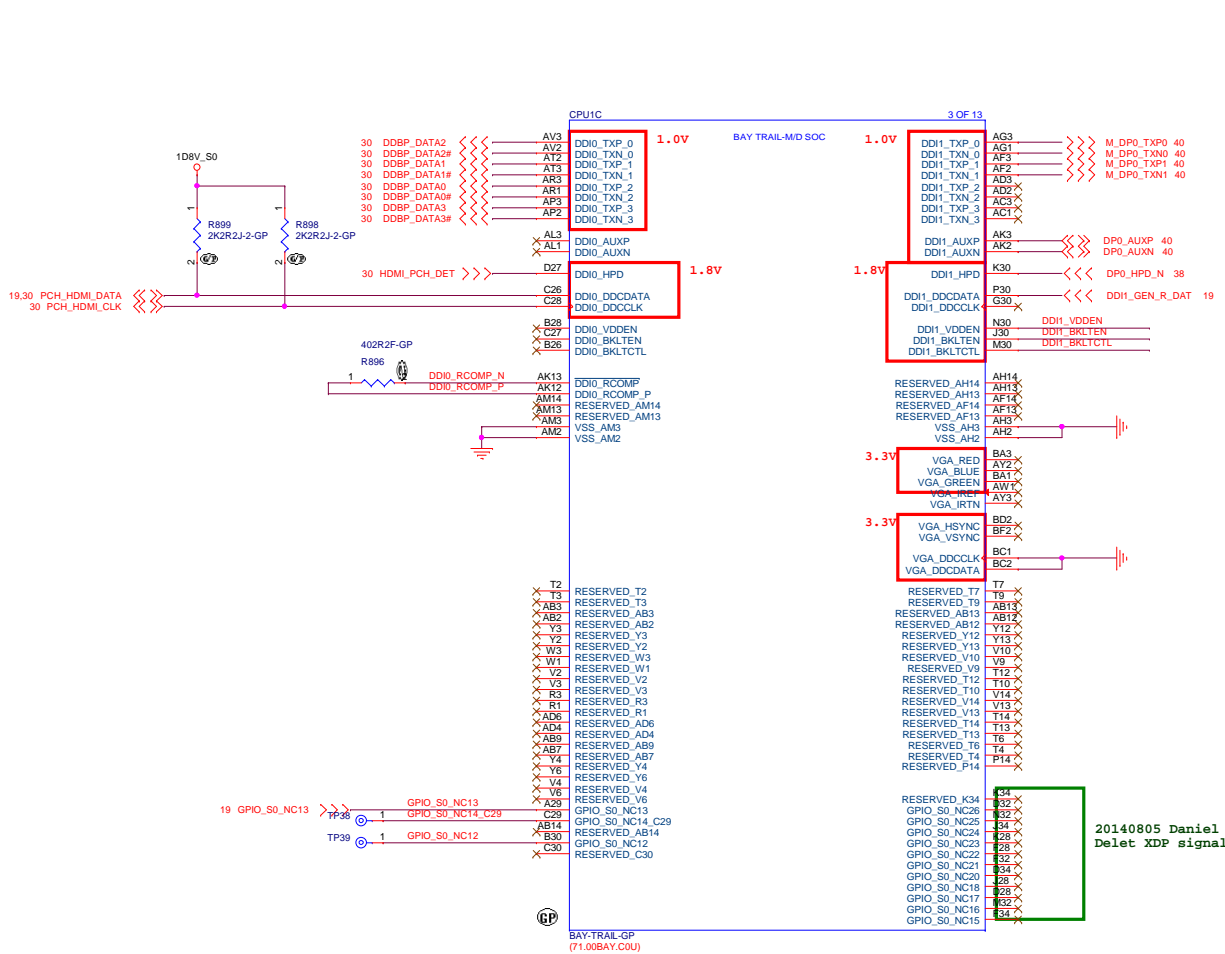
1A

Date:

Friday, September 12, 2014

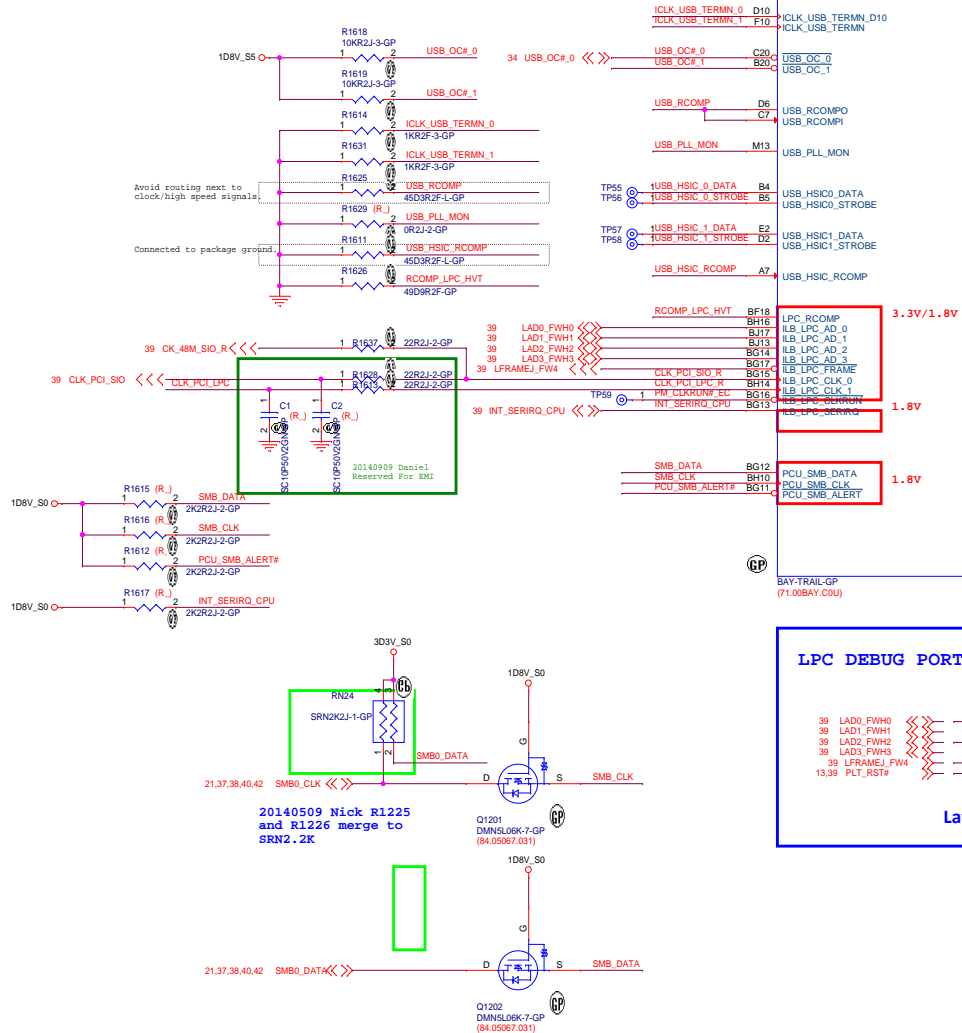
Sheet

10 of 62

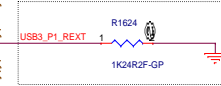


USB Table

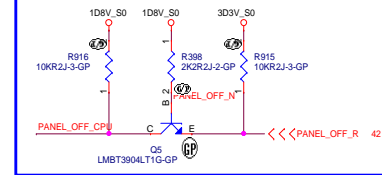
Pair	Device
0	USB3.0 Port 0 (USB352)
1	USB HUB IC
2	CAM1
3	Delete TOUCH1



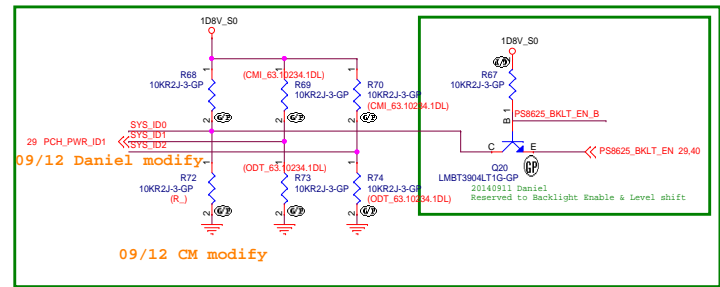
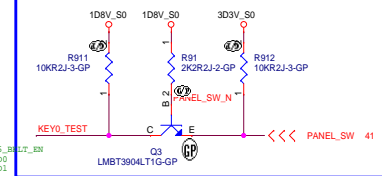
Make sure the signal routing is as short as possible
and isolated from high speed data signal.
Parasitic resistance for the overall routing should be less than 100 Ω.



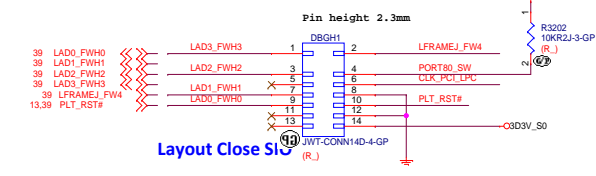
PANEL OFF



KEY TEST

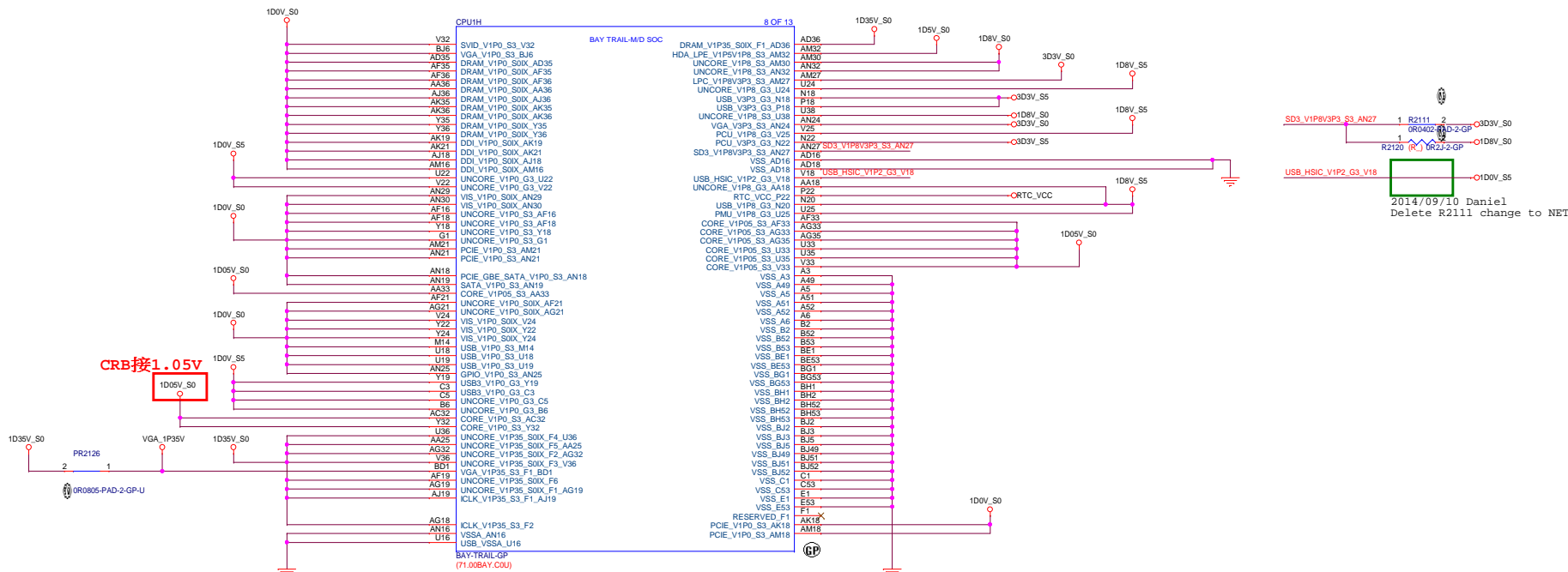


LPC DEBUG PORT

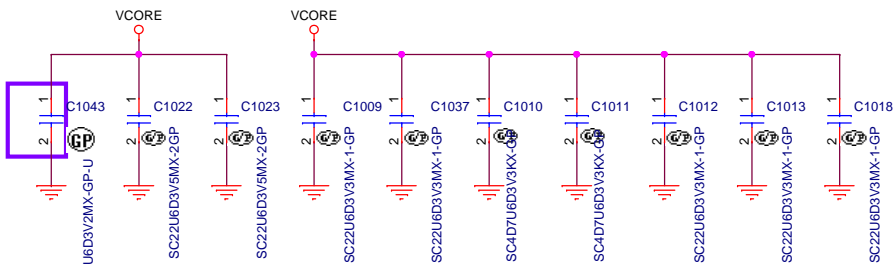


PANEL_BTN_EVENT#_CPU << PANEL_BTN_EVENT# 39

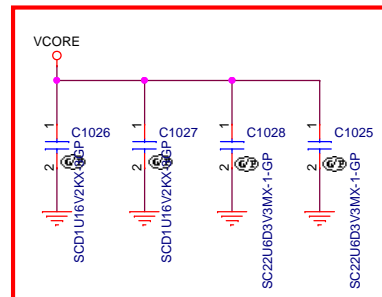




VCORE

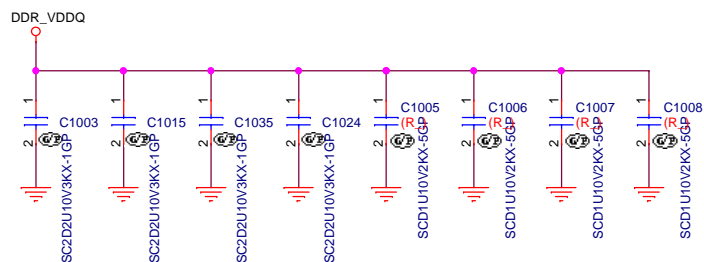


reserve the 0402 0.1u caps
on reset for EMI(5/9).

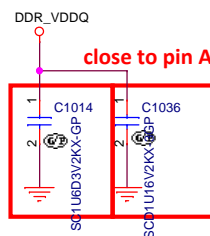


20150515 Nick add for power request

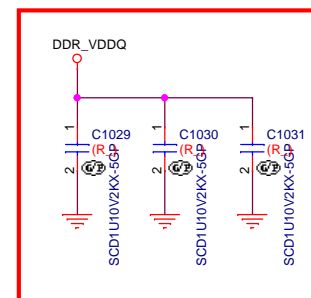
DDR_VDDQ



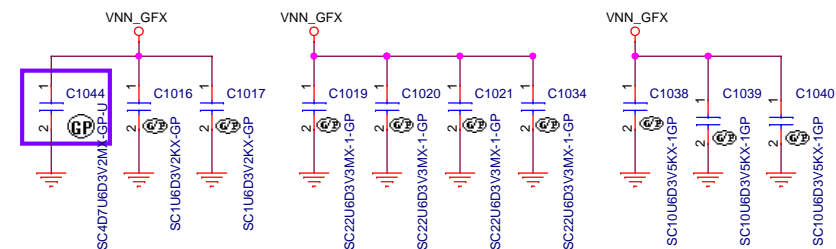
close to pin AD38 & AF38



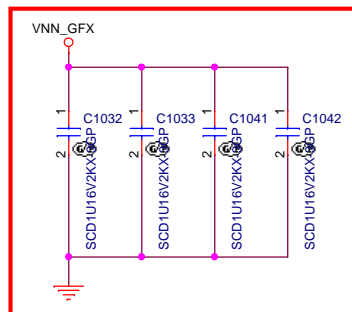
reserve the 0402 0.1u caps
on reset for EMI(5/9).



VNN_GFX



reserve the 0402 0.1u caps
on reset for EMI(5/9).



20150515 Nick add for power request

<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

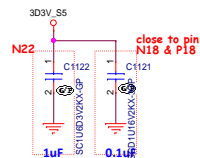
Title
CPU (POWER CAP1)

Size B Document Number
Low Cost A10

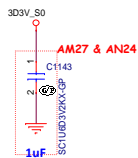
Rev
1A

Date: Friday, September 12, 2014 Sheet 16 of 62

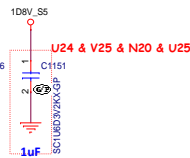
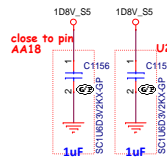
3D3V_S5



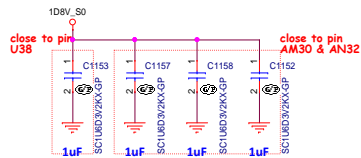
3D3V_S0



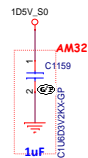
1D8V_S5



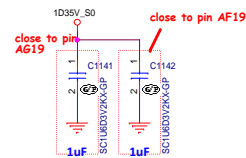
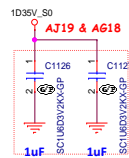
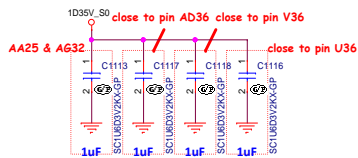
1D8V_S0



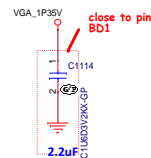
1D5V_S0



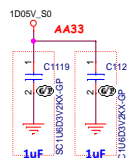
1D35V_S0



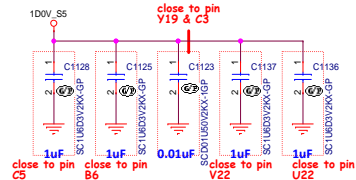
VGA_1P35V



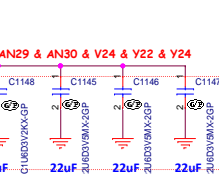
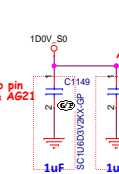
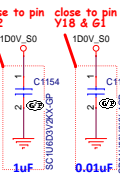
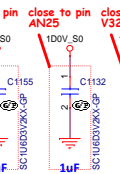
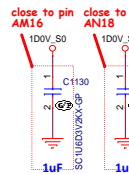
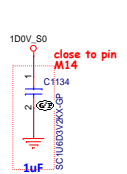
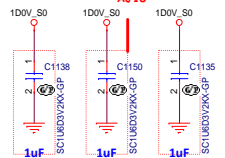
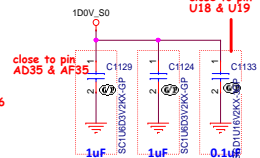
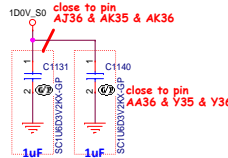
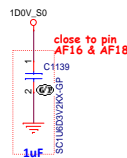
1D05V_S0



1D0V_S5



1D0V_S0



<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsinchu, Taipei

File
CPU (POWER CAP2)

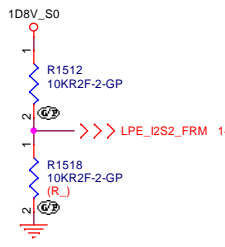
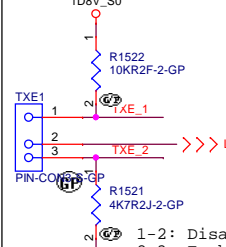
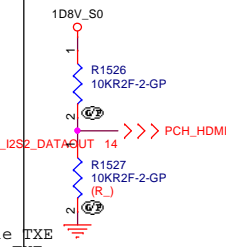
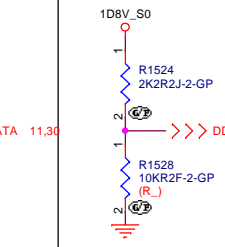
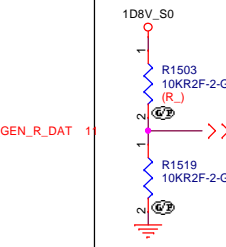
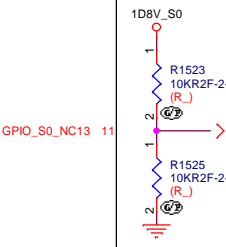
Size
Custom

Document Number
Low Cost AIO

Rev
1A

Date: Friday, September 12, 2014 Sheet 17 of 62

STRAP RESISTORS SHOULD BE PLACED CLOSE TO SOC
SHOULD BE PLACED OUTSIDE KOZ AREA

Description	BIOS Boot Selection	Security Flash Descriptors	DDI0 Detect	DDI1 Detect	DDI1 Detect	Top swap
GPIO	GPIO_S0_SC[063]	GPIO_S0_SC[065]	DDI0_DDCDATA	DDI1_DDCDATA	MDSI_DDCDATA	GPIO_S0_SC [56]
Schematic						
High	SPI	Normal Operation	DDI0 detected	DDI1 detected	DDI1 detected	
Low	LPC	Override	DDI0 not detected	DDI1 not detected	DDI1 not detected	

2.25 Hardware Straps

All straps are sampled on the rising edge of PMC_CORE_PWROK.

Table 27. Straps

Signal Name	Function	Default	Strap Exit	Strap Description
GPIO_S0_SC[63]	Legacy	1b	PMC_CORE_PWROK de-asserted	BIOS Boot Selection 0 = LPC 1 = SPI
GPIO_S0_SC[65]	Legacy	1b	PMC_CORE_PWROK de-asserted	Security Flash Descriptors 0 = Override 1 = Normal Operation
DDI0_DDCDATA	Display	0b	PMC_CORE_PWROK de-asserted	DDI0 Detect 0 = DDI0 not detected 1 = DDI0 detected
DDI1_DDCDATA	Display	0b	PMC_CORE_PWROK de-asserted	DDI1 Detect 0 = DDI1 not detected 1 = DDI1 detected
MDSI_DDCDATA	Display	0b	PMC_CORE_PWROK de-asserted	DDI1 Detect 0 = DDI1 not detected 1 = DDI1 detected

27.1.1.2 Hardware Controlled

System hardware, external to the SoC, can be used to assert or de-assert the Top-Swap strapping input signal. If the signal is sampled as being asserted during power-up then Top-Swap is active.

Note: The Top-Swap strap is an active high signal and is multiplexed with the GPIO_S0_SC[56] signal.

<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title

CPU (STRAP)

Size
A3

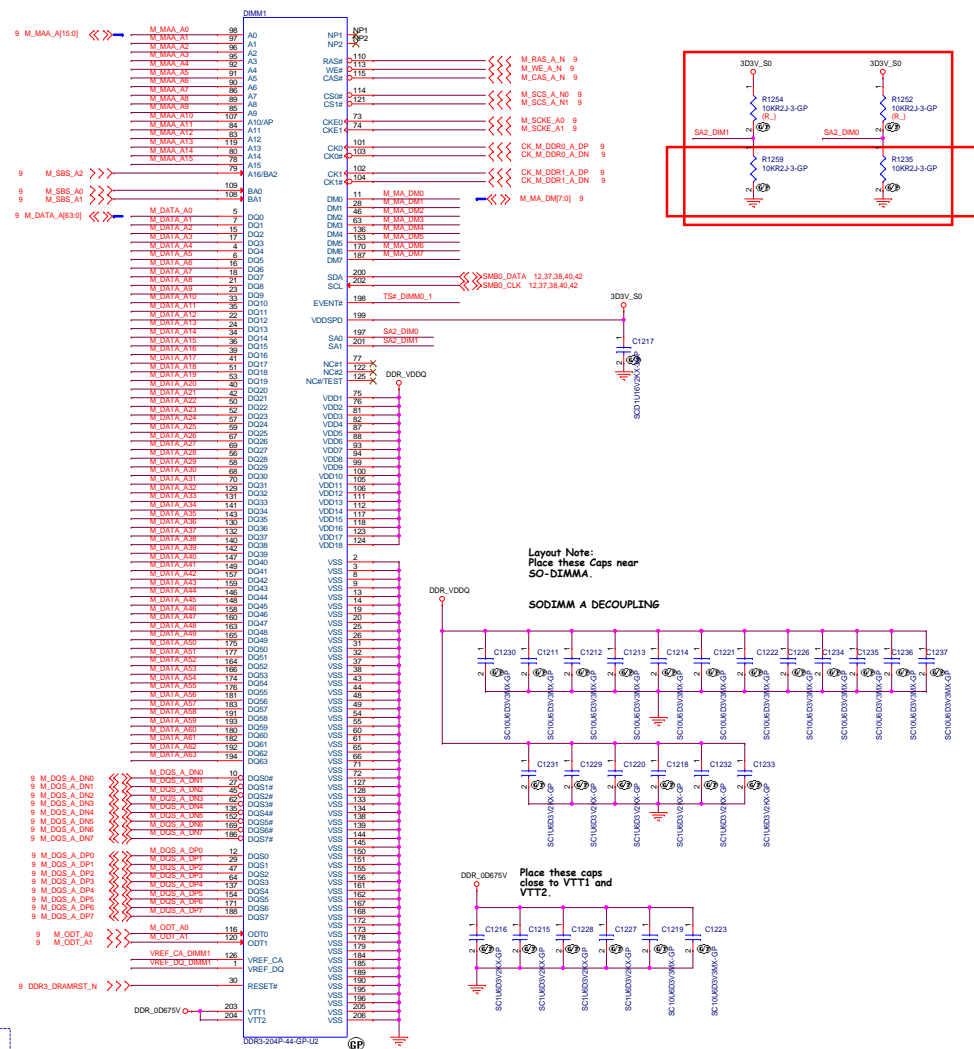
Document Number
Low Cost AIO

Rev
1A

Date: Friday, September 12, 2014


Sheet 19 of 62

TBD



TBD

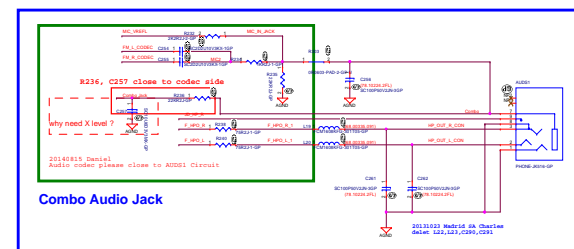
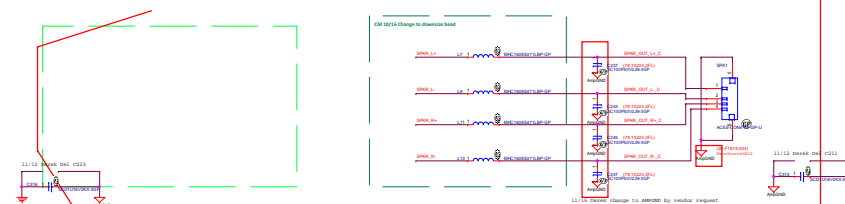
<Core Design>

		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title Front BD Connector			
Size A	Document Number Low Cost AIO		Rev 1A
Date:	Friday, September 12, 2014	Sheet	22 of 62



Support iPhone ~ Mount R3018,R3020
unMount R3019,R3021

Support Nokia ~ Mount R3019,R3021
unMount R3018,R3020



SHEN_MUTE_AP_CTL
When the PC mode and Monitor mode are being switched

MUTE_AP_CTL should be low in order to avoid the noise

MUTE_AP_CTL also control when **wait_MUTE** in the PC mode Monitor mode

MUTE_AP_CTL also control when system wake from S3 to S0



Control

23 >>>

Enable Control
 Low / High
 High / No-HOTF

23 FMI_1_CODEC

23 FMI_2_CODEC

23 IMC_VSREF

23 E_HPD_A

23 E_HPD_B

14,23,39 AZ_RPT_N

23 SPWR_L+

23 SPWR_L-

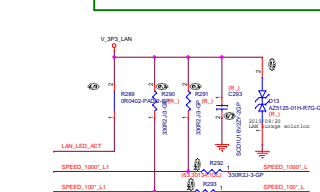
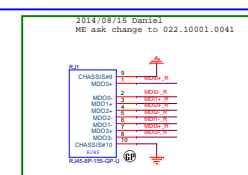
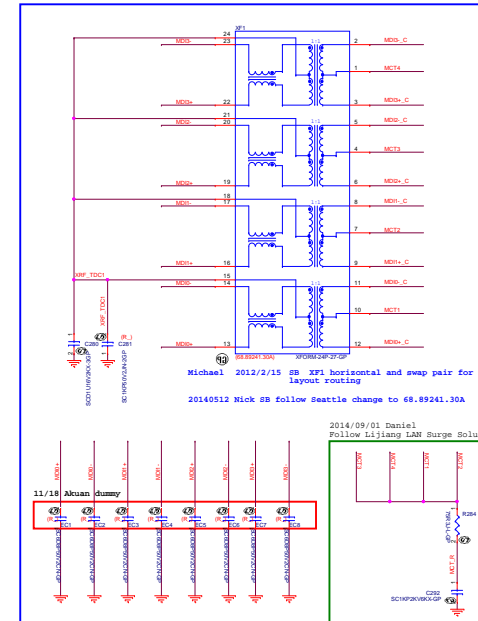
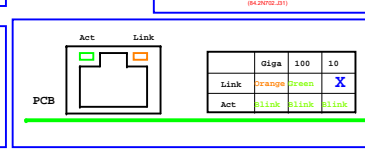
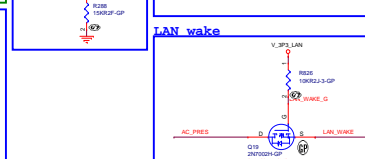
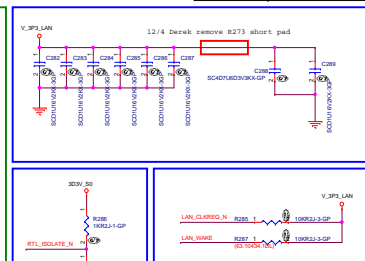
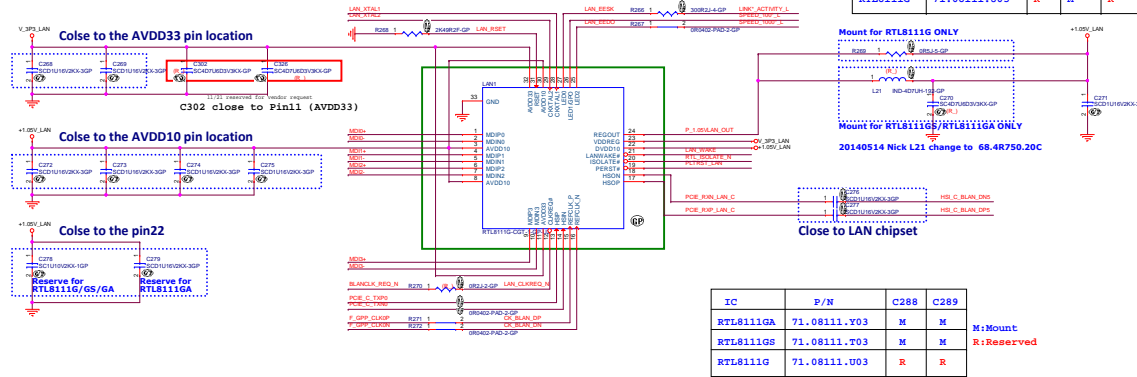
23 SPWR_R+

23 SPWR_R-

23 Control Jack

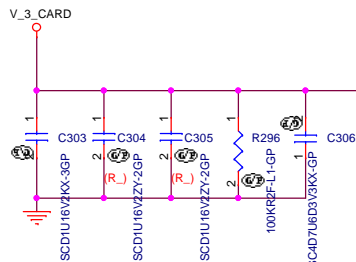
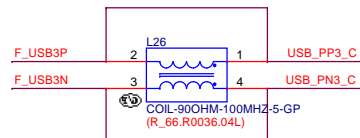
2012/08/28 sp880_5a

M:Mount
R:Reserved

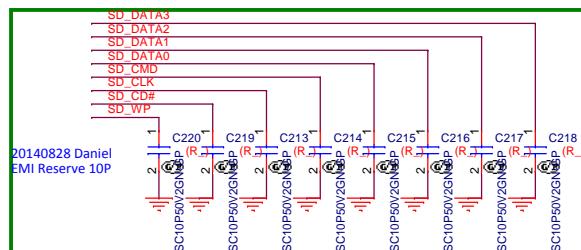
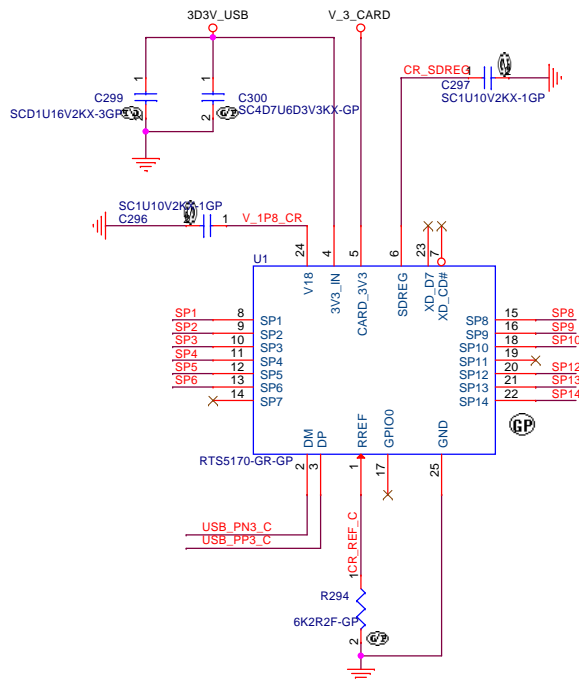


(SD only)

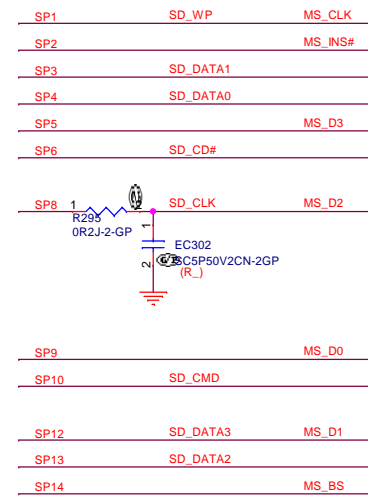
35 F_USB3P
35 F_USB3N



Without card	CD ○ ○ ○ WP
Inserted card(lock)	CD ○ ○ ○ WP
Inserted card(unlock)	CD ○ ○ ○ WP



3IN1 (MS/SD/MMC) Combo Net



Core-Designs

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsieh, Taipei

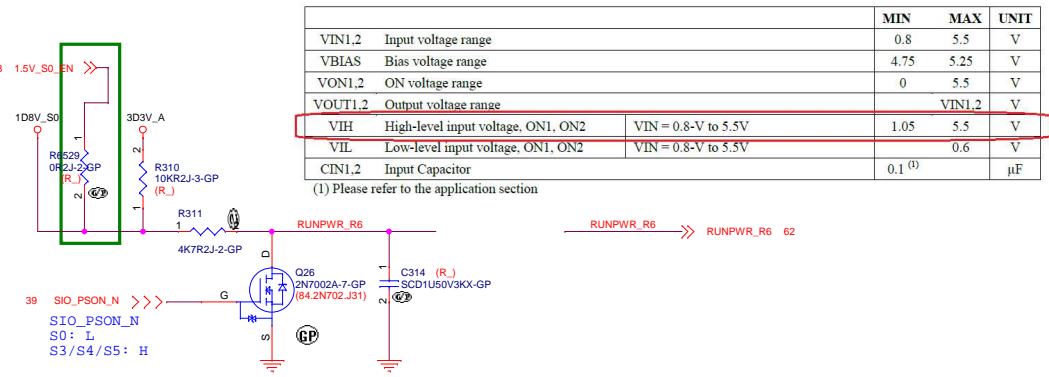
Title
RTS5170 (CARD READER)

Size
Custom Low Cost AIO

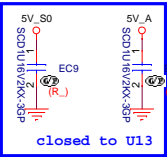
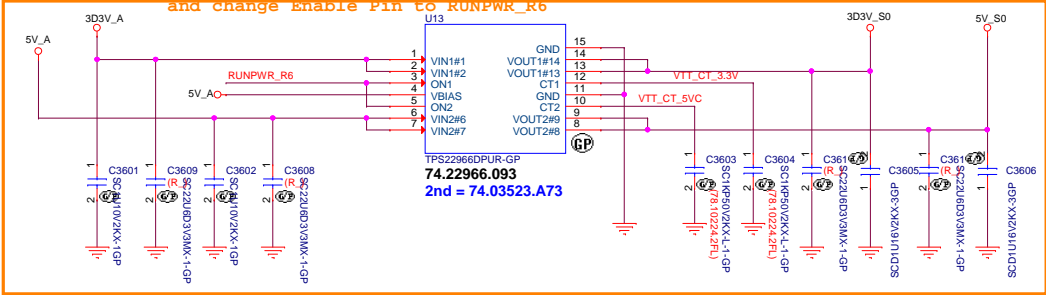
Rev
1A

Date: Friday, September 12, 2014 Sheet 26 of 62

ANNIE Run Power

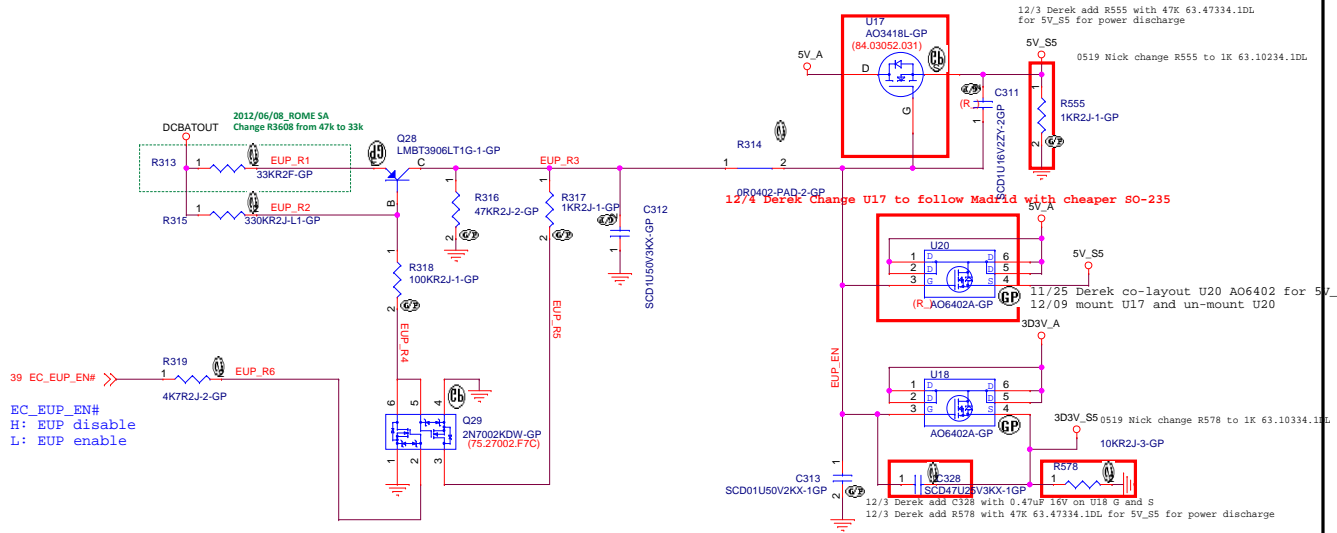


12/25 Derek
Delete U13/U15 power MOS
Add TPS22966 for 3V/5V_S0 power
1/14 Daniel Change EN pin from 12V_S0_PG
1/16 Daniel SWAP 3D3V_S0 & 5V_S0 for Layout
and change Enable Pin to RUNPWR_R6



2012/10/19 David
change from 84.04468.A37 (11.6A)
to 84.05402.B3D (7A)

EUP Power




2012/10/21 David
Removed PS_S3CNTRL

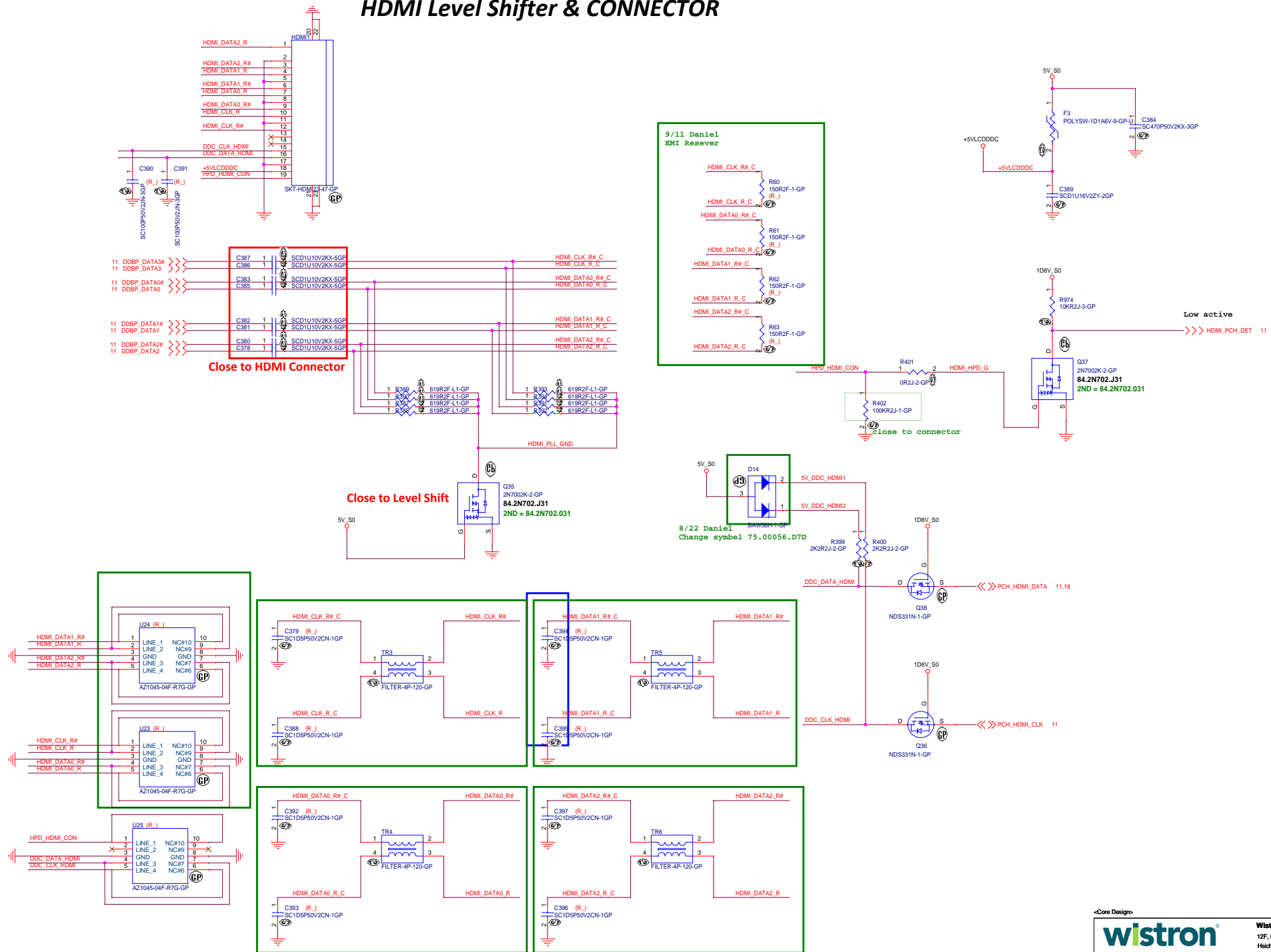
AspireLink

TBD

<Core Design>

		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title AspireLink			
Size A	Document Number Low Cost AIO		Rev 1A
Date:	Friday, September 12, 2014	Sheet	28 of 62

HDMI Level Shifter & CONNECTOR



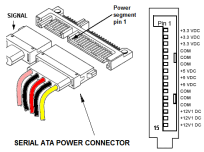
TBD

<Core Design>		wistron [®]		Wistron Incorporated	
				12F, 88, Hsin Tai Wu Rd Hsichia, Taipei	
Title					
HDMI IN					
Size	Document Number				Rev
C	Low Cost AIO				1A
Date:	Friday, September 12, 2014		Sheet	31	of 62

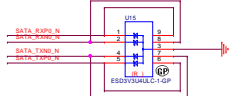
SSID = SATA

SATA HDD Connector

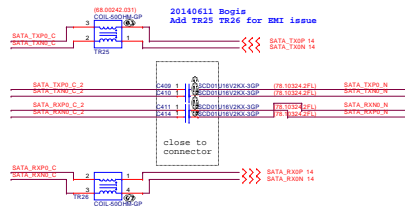
Layout: Put them together



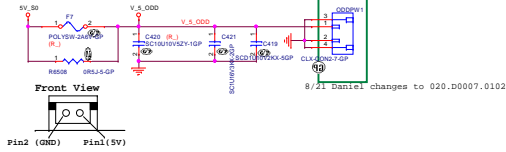
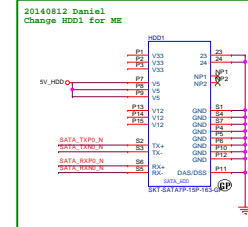
20140514 Nick add U15 TVS for RMI
20140516 Nick swap U15 net name



2012/10/5 David
Directly connected inside chip footprint for signal quality
(SA only!!!)

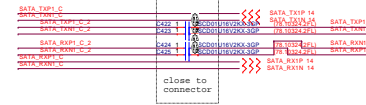


2012/10/10 David
SA create a temporary symbol (ZZ.08520.003) for re-driver co-lay,
if confirm that re-driver is required, need change symbol to
normal type (71.08520.003) , and cut short-pad inside the IC



2012/10/23 David
change to PS8520 for SATA gen3

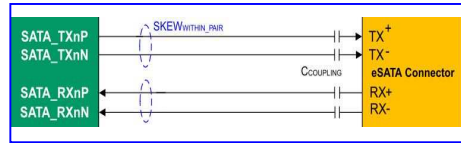
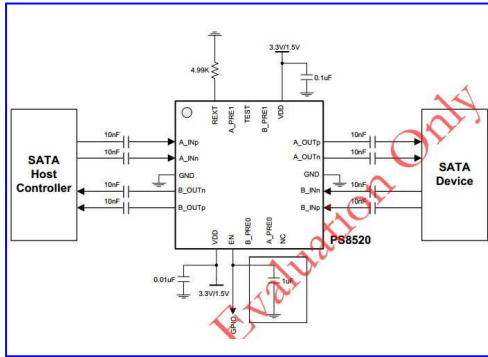
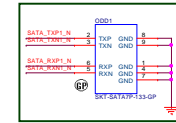
2013/05/21 David
Deleted SATA re-driver since
test PASS and to fix P/R issue



2012/10/24 David
EN pin and TEST pin can be floating for normal working.
Pin20 (REXT) should be connect to 4.99K ohm to GND

2012/10/5 David
Directly connected inside chip footprint for signal quality
(SA only!!!)

2012/10/10 David
SA create a temporary symbol (ZZ.08520.003) for re-driver co-lay,
if confirm that re-driver is required, need change symbol to
normal type (71.08520.003) , and cut short-pad inside the IC



VCC5_USB

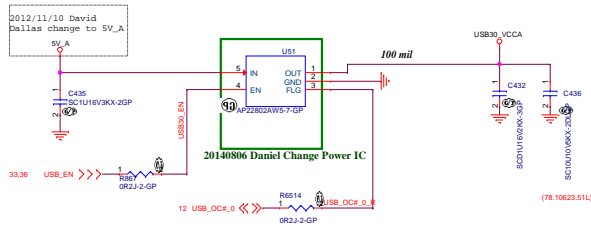


Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

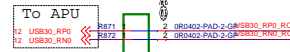
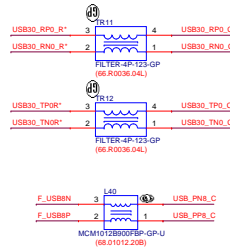
Rev
1A

Date:	Friday, September 12, 2014	Sheet	33	of	62
-------	----------------------------	-------	----	----	----

20140508 Nick change F7 to 074.07549.0099

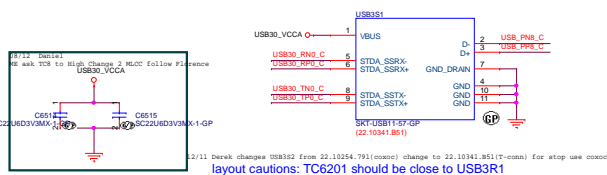
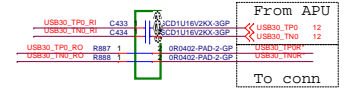


0ohm: 66.R0036.04L



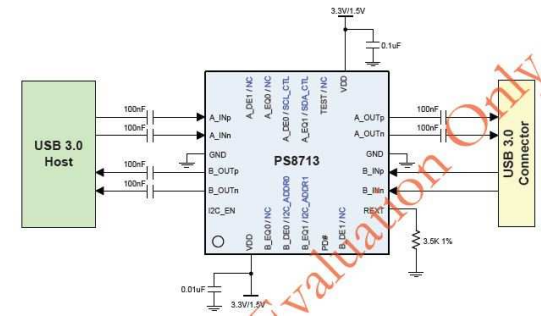
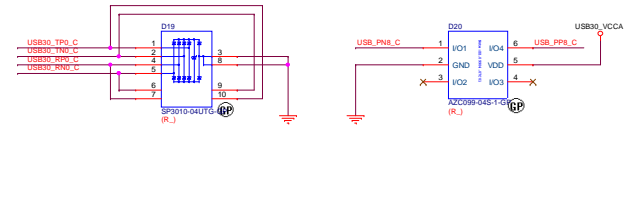
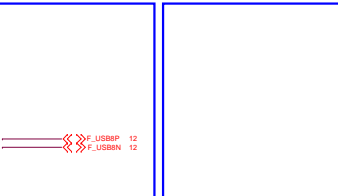
2012/07/12
If use NXP
R126,R136= 0ohm
R81=NC
If use TI
R126,R136,R81= 0ohm

2012/10/5 David
Directly connected inside chip footprint for signal quality
(SA only!!!)



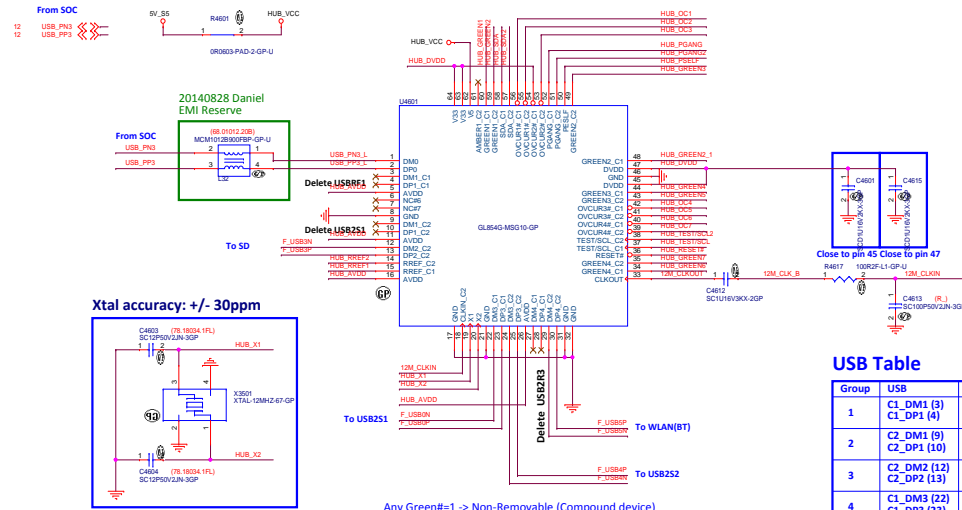
12/11 Derek changes USB302 from 22.10254.791(connc) change to 22.10341.B51(T-conn) for stop use connc
layout cautions: TC6201 should be close to USB3R1

USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+ SuperSpeed RX
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+ SuperSpeed TX



GL850G
 Enable/Disable USB output port: D+/D- pull high 1K to disable USB port
 Set USB port to be internal (non-removable): set OC pin is floating
 Set USB port to be external (removable): set OC pin is non-floating (pull high 10K to 3.3V or USB OC#)

GL852G
 Enable/Disable USB output port: setting by EEPROM
 Set USB port to be internal (non-removable) or external (removable): setting by EEPROM



Any Green#1 -> Non-Removable (Compound device)

Non-Removable X 1 1 1 1 1 1

Note -- x : Not support
 1 : Pull up 15K to DVDD
 PGreen2 & PGreen3 do not set to 1 concurrently

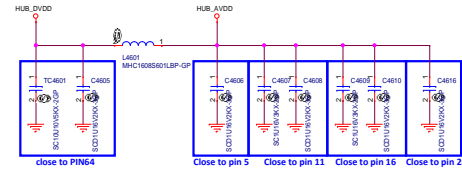
USB Table

Group	USB	Device	
1	C1_DM1 (3) C1_DP1 (4)	USB251	Delete
2	C2_DM1 (9) C2_DP1 (10)	USB251	Delete
3	C2_DM2 (12) C2_DP2 (13)	SD	internal
4	C1_DM3 (22) C1_DP3 (23)	USB251	external
5	C2_DM3 (24) C2_DP3 (25)	USB252	external
6	C1_DM4 (27) C1_DP4 (28)	USB253	Delete
7	C2_DM4 (29) C2_DP4 (30)	MINI1	internal

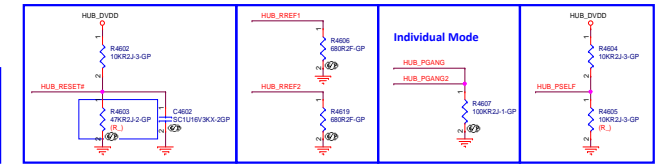
36 F_USB4P USB252
 36 F_USB4P USB251
 37 F_USB4P MINI1
 37 F_USB4P SD

Internal Power

(Hub Internal VR output from pin 63/64 V33 = HUB_DVDD)



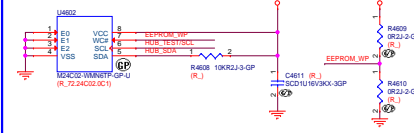
Fine tune resistor value for USB driving
 590ohm: 64.59005.6DL



HUB_PSELF = 1 if self-powered
 HUB_PSELF = 0 if bus-powered

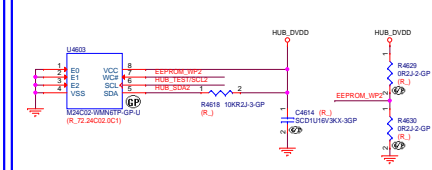
EEPROM

Option:
 24C02 for VID, PID,
 Strapping, Configuration.
 Option for 1-tier hub

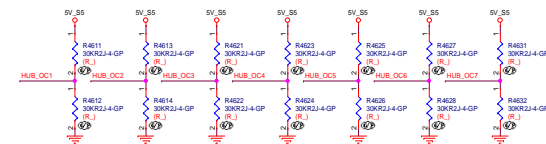


EEPROM

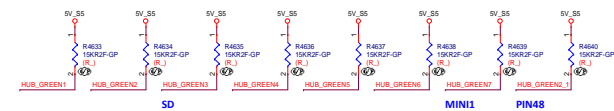
Option for 2-tier hub



Over Current



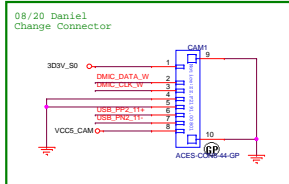
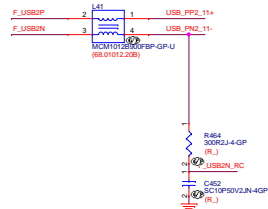
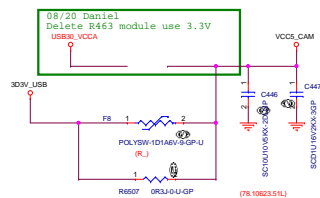
Green LED



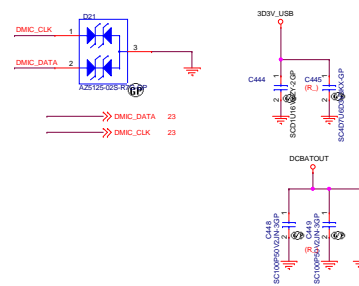
©Core Design

```
SSID =USB2.0
```

USB Port2 -> WEB CAM



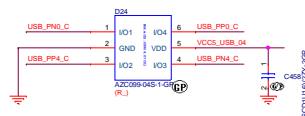
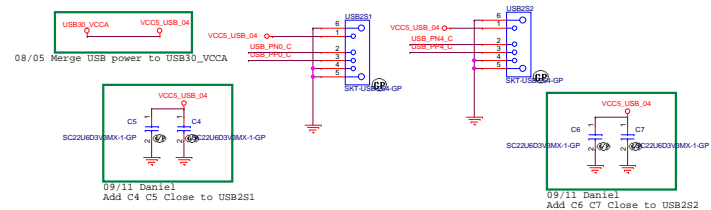
DMIC Connector



USB Port 1 -> Delete TOUCH

Max touch Connector Pin Definition		TPK touch Connector Pin Definition	
PIN NO.	PIN Name	PIN NO.	PIN Name
1	VUSB	1	VUSB
2	D-	2	D-
3	D+	3	D+
4	GND	4	GND
5	Shield	5	Shield

USB Port -> Side I/O



SSID = Wireless and Bluetooth

Mini Card Connector(Wireless LAN+BT)

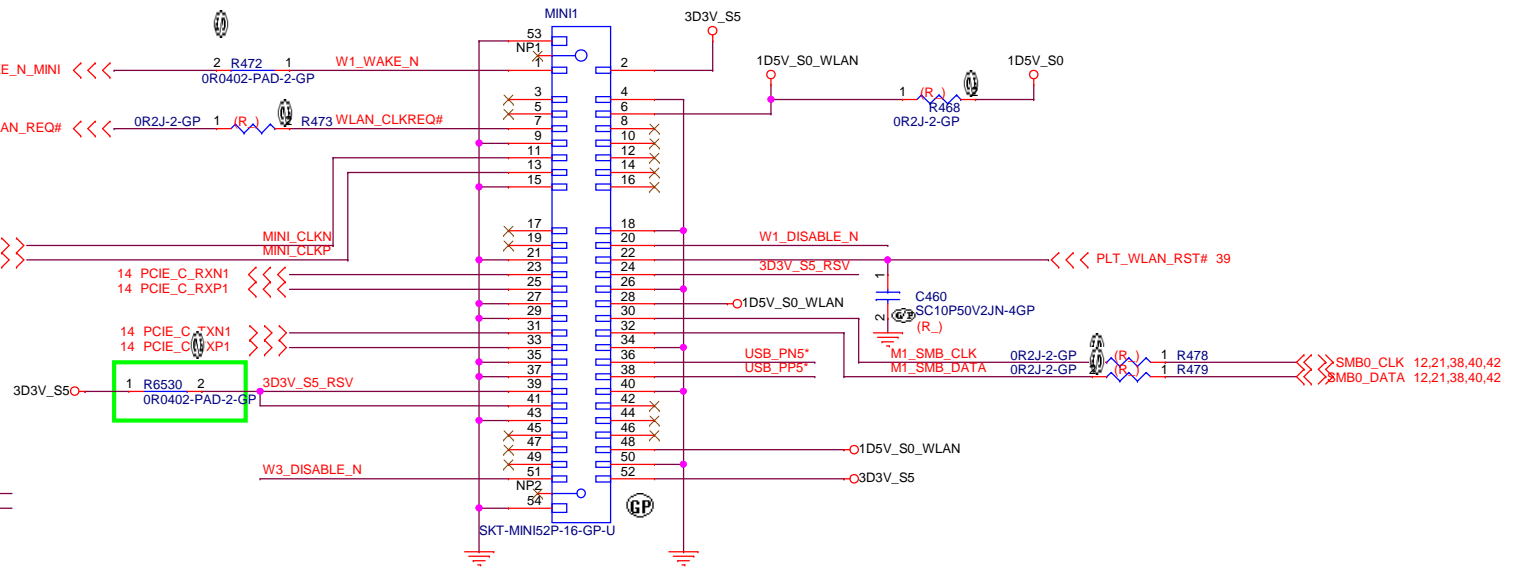
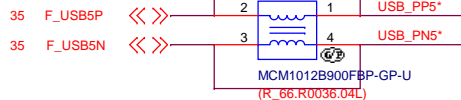
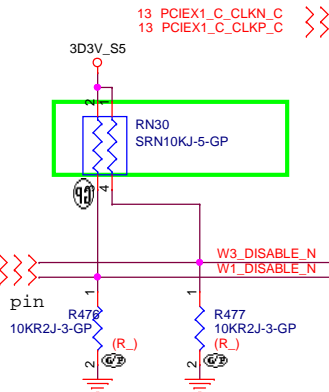
20140509 Nick R470
and R471 merge to
SRN0R

H: enable
L: disable

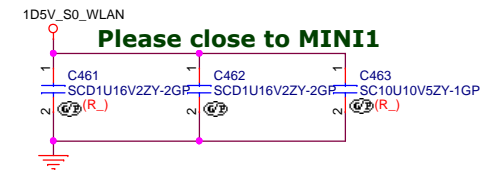
BT disable pin

39 W3_DISABLE_N
39 W1_DISABLE_N

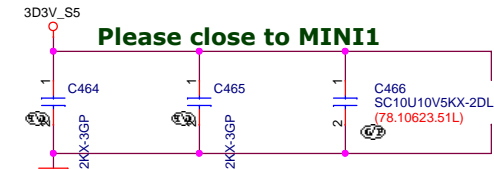
Wireless disable pin



Please close to MINI1



Please close to MINI1



<Variant Name>

wistron

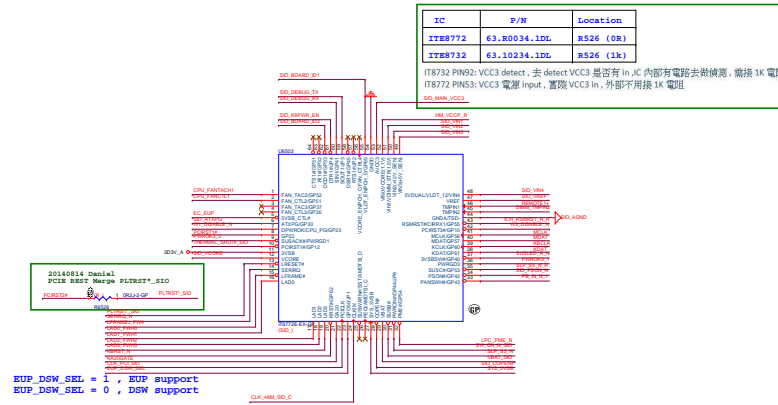
Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

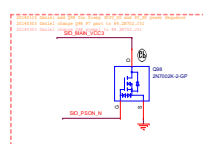
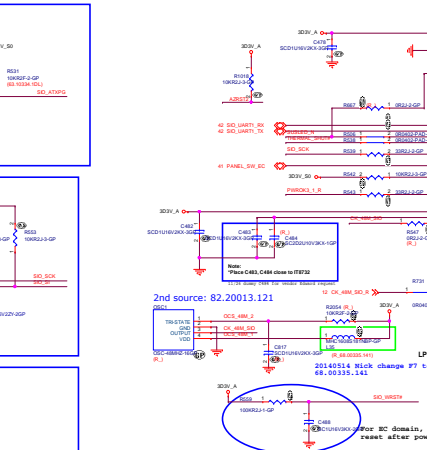
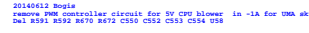
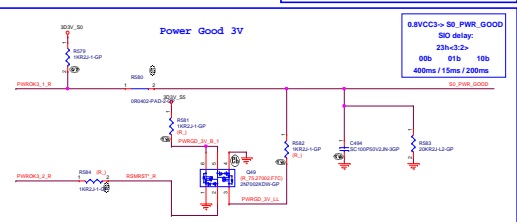
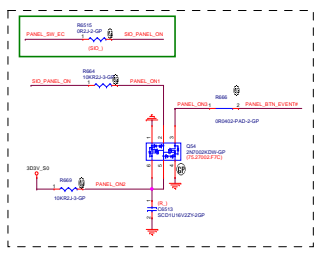
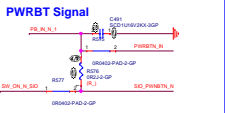
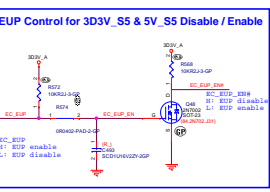
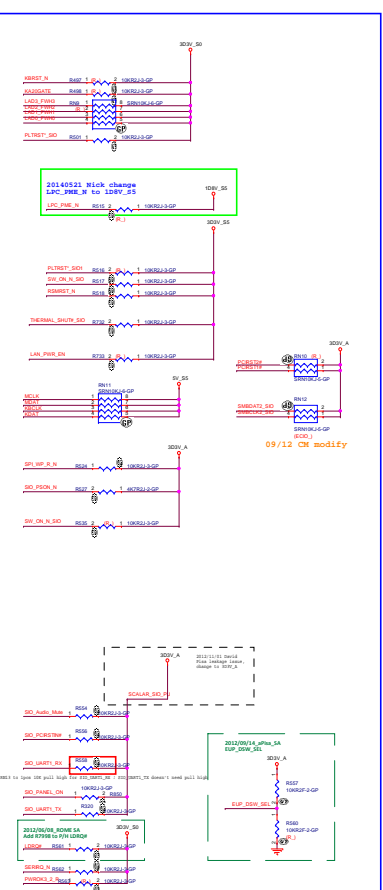
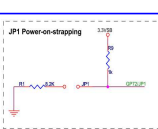
Title
MINI PCIE CARD (WLAN/BT)

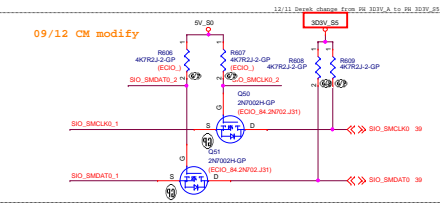
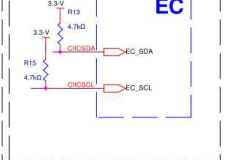
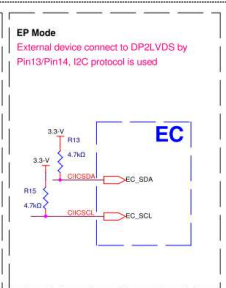
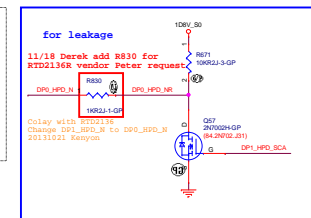
Size
Custom
Document Number
Low Cost AIO

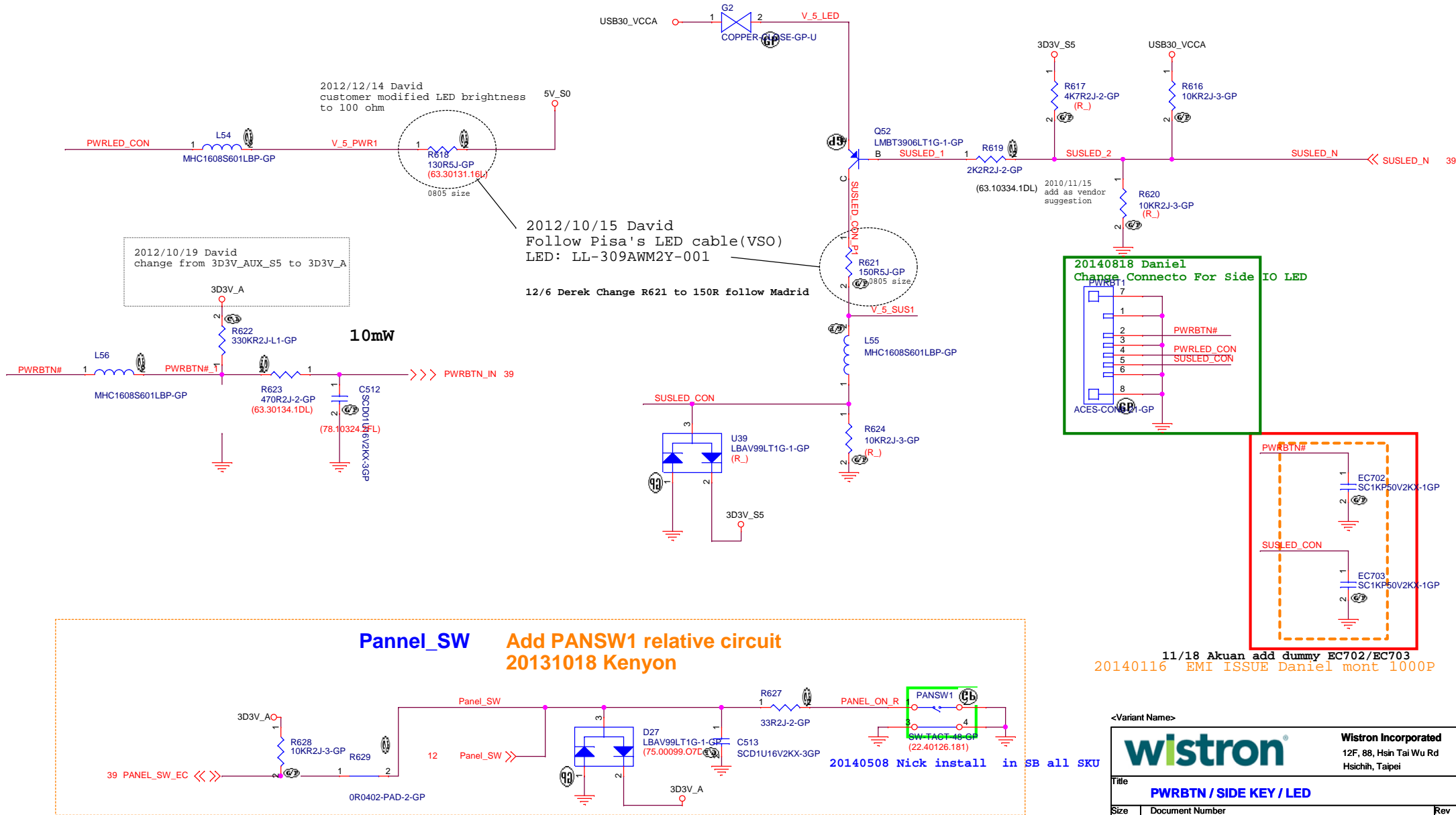
Rev
1A


Date: Friday, September 12, 2014 Sheet 37 of 62



[illegible]






<Variant Name>		Wistron Incorporated	
		12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title			
PWRBTN / SIDE KEY / LED			
Size	Document Number	Rev	
Custom	Low Cost AIO	1A	
Date:	Friday, September 12, 2014	Sheet	41 of 62

TBD

<Variant Name>



Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title

XDP

Size
B

Document Number
Low Cost AIO

Rev
1A

Date: Friday, September 12, 2014Sheet 42 of 62

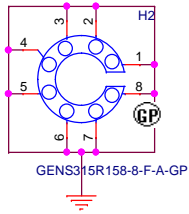
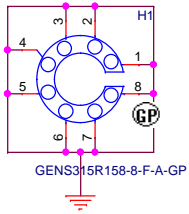
TBD

<Core Design>

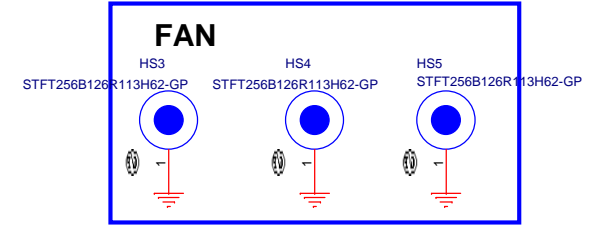
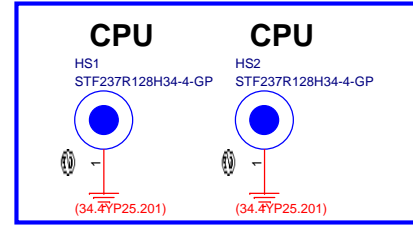
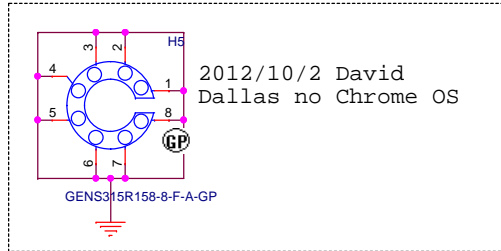
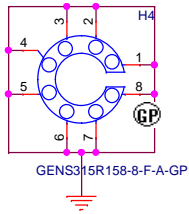
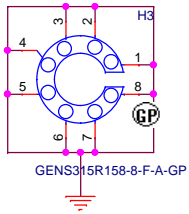


Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsinchu, Taipei

Title		
SCALAR POWER		
Size	Document Number	Rev
Custom	Low Cost AIO	1A
Date: Friday, September 12, 2014 Sheet 43 of 62		



ZZ.SCREW.541



<Core Design>

wistron		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title		STAND OFF / HOLE / EMI CAP	
Size B	Document Number Low Cost AIO	Rev 1A	
Date:	Friday, September 12, 2014	Sheet	44 of 62

Material part

LGA115x CPU SOCKET Symbol

Vendor: LOTES
P/N: 22.78003.011

Vendor: FOXCONN
P/N: 22.78006.001

Vendor: LOTES
P/N: 22.78002.011
Thickness: max 2.2mm (含mylar及螺孔高)

Vendor: FOXCONN
P/N: 22.78006.011
Thickness: 2.0mm (含mylar)

Vendor: LOTES
P/N: 22.78005.171

Vendor: FOXCONN
P/N: 22.78005.161

2013/03/19 David
Removed CPU socket & back plate & cover

LABEL



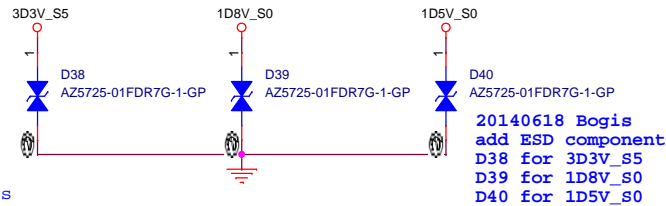
LBL1
LABEL
(40.3BZ24.001)

LBL2
LABEL
(R_)

LBL3
LABEL
(R_)

MB serial NO# and MAC address
40.3KP03.001 -> 35 x 15mm
45.41107.011 -> 70 x 8mm
45.41115.001 -> 34 x 13.5mm for aDallas
40.3BZ24.001 -> 30 x 15mm

09/24 Daniel
Change to 30x15 mm



Vendor: LOTES
P/N: 22.78005.171

Vendor: FOXCONN
P/N: 22.78005.161

Stand-off

2013/03/19 David
Removed Stand-off
since already exist

34.3KF01.001 for 5.2mm slot 62.10043.G11
34.3HJ03.001 for 9.0mm slot 62.10043.E41

HeatSink Symbol

2013/03/19 David
Removed HeatSink

Vendor
P/N:
60.3ET05.001
60.3ET05.011
60.3ET05.021

Battery Symbol



BTT2
BATTERY CR2032
(23.20068.001)

Vendor
P/N:
23.20068.001
23.20023.311
23.22063.001

PCB Symbol

<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title
HeatSink/Battery/etc

Size B Document Number
Low Cost A10


Rev
1A

Date: Wednesday, September 24, 2014 Sheet 45 of 62


TBD

TBD

<Core Design>

		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title		GPU(2/5): IFB(10)	
Size	Document Number	Rev	
Custom	Low Cost A10	1A	
Date:	Friday, September 12, 2014	Sheet	47 of 62

TBD

<Core Design>			
		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title			
GPU(3/5): MEMORY FBA			
Size C	Document Number Low Cost A10		Rev 1A
Date:	Friday, September 12, 2014	Sheet	48 of 62

GPIO	GPIO17
GPIO 0	FWK_PRMTS_DECLAREDBG Service
GPIO 1	ARMV750_CTL
GPIO 3	UNUSED
GPIO 4	UNUSED
GPIO 5	Reserved
GPIO 6	FW_CLAMP_TSL_NEO
GPIO 7	3DVIEW(UNUSED)
GPIO 8	GPU Control
GPIO 9	GPU Thermal Alert
GPIO 10	FSB Write Control
GPIO 11	NOVODS PREL_NEO
GPIO 12	FWK_PRMTS_Video
GPIO 13	UNUSED (Not Set in VIDEO)
GPIO 14	N/A on Package
GPIO 15	N/A on Package
GPIO 16	N/A on Package
GPIO 17	N/A on Package
GPIO 18	N/A on Package
GPIO 19	N/A on Package
GPIO 20	N/A on Package
GPIO 21	N/A on Package

Pin Name	Normal Function	I/O	Functional Description	Recommended Default Pinup or Pull-down
GNP01	MEM_VDD_P1M0	I/O	16-Mbit SRAM	16k Ω pull-up to boot
GNP02	MEM_VDD_P1M0	I/O	16-Mbit SRAM	100k Ω pull-up to boot
GNP03	LED_VCC_P1M0	I/O	Panel Backlight Enable	LED_VCC_P1M0: 100k Ω pull-up to boot
GNP04	LED_BLED_P1M0	I/O	Panel Backlight Enable	100k Ω pull-up to boot
GNP05	Reserved			
GNP06	PS1_CLAMP_TREQ2	I/O	Active-low PS1 clamp toggle	
GNP07	SDIO_CLK	I/O	3.3V 100-MHz signal	100k Ω pull-up
GNP08	OVER1	I/O	Active-low Thermal Alert Temperature	100k Ω pull-up
GNP09	ALERT1	I/O	Active-low Thermal Alert Temperature	100k Ω pull-up
GNP10	MEM_VREF_CTL1	I/O	Memory VREF Control	100k Ω pull-down
GNP11	MEM_VREF_CTL2	I/O	Memory VREF Control	100k Ω pull-down
GNP12	PS1_VREF_L1	I/O	PS1 VREF signal	100k Ω pull-up
GNP13	PS1	I/O	PS1 VREF signal	PS1: 10k Ω pull-up to enable phase.
GNP14	PPS_A1	I/O	PPS A1 input for PPS, as Data Output for the PPAS (PPS A1 Out) (See Table 1)	See Figure 76
GNP15	IO_P0	I/O	HS6 Pad Protect for I/O P0	See Figure 76
GNP16	PPN_A1	I/O	2X Frame Lock signal	See Figure 76
GNP17	IO_P1	I/O	HS6 Pad Protect for I/O P1	See Figure 76
GNP18	IO_P2	I/O	2X Frame Lock signal	See Figure 76
GNP19	PPN_P0_P1_P2	I/O	HS6 Pad Protect for I/O P0 or I/O P1 used as DataOutput	See Figure 76
GNP20	Reserved			
GNP21	Reserved			

GPIO0, GPIO6 is for GC6 feature, no need to connect since this project won't support GC6.
GPIO1 is for FB voltage control, no need to connect since the FBVDDQ is 1.5V for all P-States.
GPIO12 : High->AC Mode,Low->Battery Mode enter slow down functionpull for power saving.Recommand:Pull-High for AC mode
GPIO13 PSI :Change Phase from two to one, and then enter slow down functionpull for power saving.

QVL1: Hynix (KN.2GB0G.038)+R488, R490, R489, R925(64.10025.6DL)
QVL2: Micron (KN.2GB04.022)+R483, R490, R929, R934 (64.10025.6DL)

PIN NAME	BINARY BRINGUP
STRAP0	3G0I_PADCFG_LUT_ADR0
STRAP1	3G0I_PADCFG_LUT_ADR1
STRAP2	3G0I_PADCFG_LUT_ADR2
STRAP3	3G0I_PADCFG_LUT_ADR3
STRAP4	PCI_MAX_SPEED
ROM_SCLK	SMB_ALT_ADDR
ROM_S1	SMB_VENDOR
ROM_S0	VGA_DEVICE

Configuration	Vendor	Storage	FBVDD/ FBIDDQ	Manufacturer Part Number	Max Speed K (MHz)	Memory Data Code Minimum	Status
128Mx 16 DDR3	Micron	0x1	1.5 V/ 1.5 V	MT41J128M16JT-095GxK	1000	1150	Production Candidate
				MT41J128M16JT-107GxK	900	1150	Production Candidate
	Samsung	0x5	1.5 V/ 1.5 V	K4V2G1646E-8C1A	1000	1204	Production Candidate
				K4V2G1646E-8C11	900	1204	Production Candidate
	Hynix	0x6	1.5V/ 1.5V	H5TQCG63DFR-10C	1000	11/A	Production Candidate
				H5TQCG63DFR-11C	900	11/A	Production Candidate

Configuration	Vendor	Strap	FBVDD/ FBVDDQ	Manufacturer/ Part Number	Max Speed CK (MHz)	Memory Data Code Aluminum	Status
256M-16 DDR3	Samsung	0x0	1.5 V/ 1.5 V	K4H46G1646B-11C1	900	N/A	Production Candidate
	Micron	0x0	1.5 V/ 1.5 V	MT41K256M16HA- 107G-E	900	N/A	Production Candidate
	Hynix	0x3	1.5V/ 1.5V	H5TQ4G63MFR-11C	900	N/A	Production Candidate
		0x4		H5TQ4G63AFR-11C		N/A	Prod-Products Candidate

Strap Pin Name	Strap Mapping	Resistance	Polarity
ROH_SCL	SUB_A12_ADR	10k Ω	Pull-down to GND
ROH_SI	SUB_VDDIO	10k Ω	Pull-up to 3V3 if VBIOS ROH present Pull-down to GND if no VBIOS ROM
ROH_S0	VGA_DEVID	10k Ω	Pull-down to GND (no display)
STRAP0	RAH_CFG[0]	10k Ω	See Hoba below
STRAP1	RAH_CFG[1]	10k Ω	See Hoba below
STRAP2	RAH_CFG[2]	10k Ω	See Hoba below
STRAP3	RAH_CFG[3]	10k Ω	See Hoba below
STRAP4	PCIE_MAX_SPEED	10k Ω	Pull-down to GND

THERMAL PROTECTION

Mount	Un-mount	VRAN Type	P/N
R488 ~ R490 R489 ~ R924	R483 ~ R486 R429 ~ R934	Rybnx 1GHz H57C2G63FF-11C	KN.2GB00.0
R483 ~ R490 R929 ~ R934	R486 ~ R486 R489 ~ R924	MICRON 1GHz MT4712L28M163T-093G:K	KN.2GB04.0
R488 ~ R486 R489 ~ R924	R483 ~ R490 R429 ~ R934	SAMSUNG 1G K4W2G1646G-BC1A	KN.2GB08.0

VRAM Type		P/N	0	1	2	3
Hynix 1G		KN.2GB0G.038			V	V
H5TC2G63FFR-11C		72.52G63.N0U	V	V		


		VRAM ID [0-3]:			
VRAM Type	P/N	0	1	2	3
Micron 1G MT41J128M16JT-093G:K	KN.2GB04.022	V			
	72.41128.I0U		V	V	V

		VRAM ID [0-3]:			
VRAM Type	P/N	0	1	2	3
SAMSUNG 1G K4W2Q1646Q-BC1A	KN.2GB0B.040		V	V	V
		V			

		Wistron Incorporated 12F, 88, Hsin Tai Wusid Hsinchu, Taipei	
GPU(45): GP101STRAP			
Doc Cust	Document Number Low Cost AIO	Rev 1A	
Ver 1.00	Effective September 13 2014	Release 23 of 62	

KN.2GB0B.041

TBD

<Core Design>			
		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title			
GPU(5/5): PWR/GND			
Size	Document Number	Rev	
C	Low Cost A10	1A	
Date:	Friday, September 12, 2014	Sheet	50 of 62

QVL1: Hynix (KN.2GB0G.038)+R221, R220, R231, R238 (64.10025.6DL)
QVL2: Micron (KN.2GB04.022)+R234, R238, R228, R219 (64.10025.6DL)

CHANNEL A:1GB DDR3

KN.2GB0G.038	2Gb	DDR3	128M*16	900MHz	SDRAM	FBGA96P	Hynix	-	H5TC2G63FFR-11C
KN.2GB04.022	2Gb	DDR3	128M*16	900MHz	SDRAM	FBGA96P	Micron	-	MT41J128M16JT-093G:K

VRAM Type	P/N
Hynix 1G H5TC2G63FFR-11C	KN.2GB0G.038
VRAM Type	P/N
Micron 1G MT41J128M16JT-093G:K	KN.2GB04.022

TBD

FBCLK Termination place on VRAM side

128M*16 VRAM
KN.2GB0B.040 - Samsung K4W2G1646Q-BC1A
KN.2GB0G.038 - Hynix H5TC2G63FFR-11C

ORDERING INFORMATION

Part No.	Power Supply	Clock Frequency	Data Rate	Interface	Package
H5TC2G63FFR-11C	VDD/VDDQ=1.35V	900MHz	1.8Gbps/pin	SSTL-15	96ball FBGA
	VDD/VDDQ=1.5V	1.0Ghz	2.0Gbps/pin		
H5TC2G63FFR-11C	VDD/VDDQ=1.5V	1.1Ghz	2.2Gbps/pin		

Note) 1.35v speed part provides backward compatibility with the 1.5V DDR3.

RMA_CFG [3:0]
Samsung - K4W2G1646E-BC11 (1000MHz) [0101]
Micron - MT41J128M16JT-093G:K (1000MHz) [0001]

1. Ordering Information

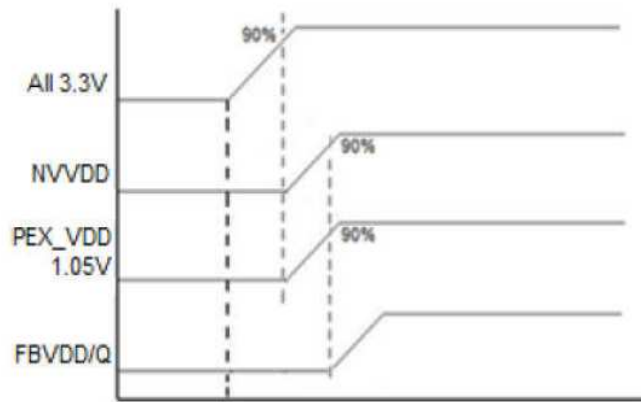
[Table 1] Samsung 2Gb gDDR3 Q-die ordering information table

Organization	gDDR3-1600(11-11-11)	gDDR3-1866(13-13-13) ²	gDDR3L-1866(13-13-13) ²	gDDR3-2133(14-14-14) ²	Package
VDD	1.5V	1.5V	1.35V	1.5V	
128Mx16	K4W2G1646Q-BC12	K4W2G1646Q-BC11	K4W2G1646Q-BC1A		96 FBGA

NOTE
1. Speed bin is in order of CL, tRC, tRP.
2. Backward Compatible to gDDR3-1800(13-13-13), gDDR3-1600(11-11-11)
3. Backward Compatible to gDDR3-1600(11-11-11)

TBD

3.3V-->NVVDD&PEX_VDD(+V_VGA_CORE&+V_1P05_VGA)-->FBVDD/Q(+V_1P5_VGA)



Notes: - All 3.3V includes all rails powered at 3.3V
- PEX_VDD 1.05V includes all rails that are shared

<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

Title
GPU_POWER Sequence

Size B Document Number
Low Cost A10

Rev
1A

Date: Friday, September 12, 2014 Sheet 52 of 62

TBD

2014/4/29 Nick change from 5V_S0 to 5V_S5

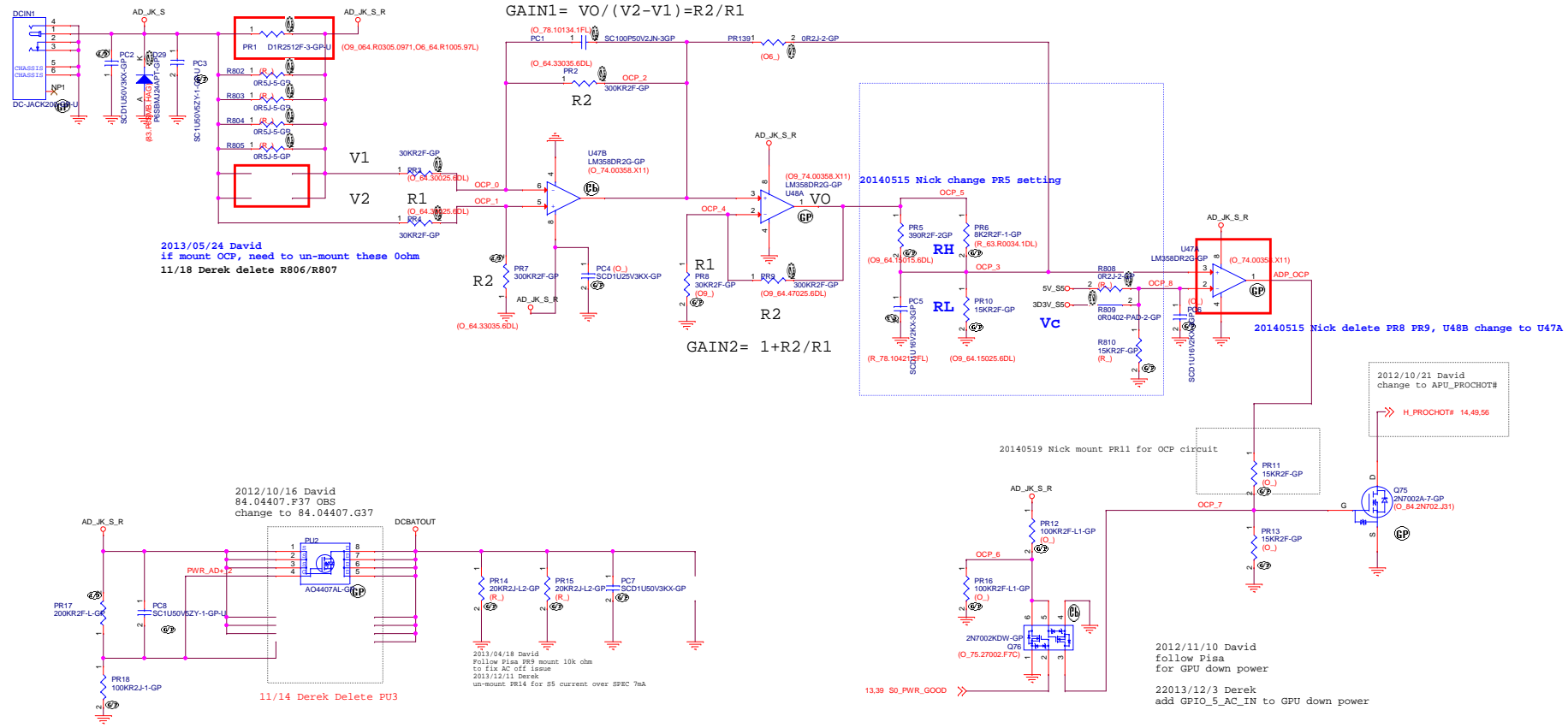
TBD

ANNIE solution

20140515 Nick change for OCP setting

SIZE 2512
0.010HM 2W

$$\text{GAIN1} = \text{VO} / (\text{V2} - \text{V1}) = \text{R2} / \text{R1}$$



<Variant Name>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsinchu, Taipei

File
PWR_DCIN JACK

Size
Custom
Low Cost AIO

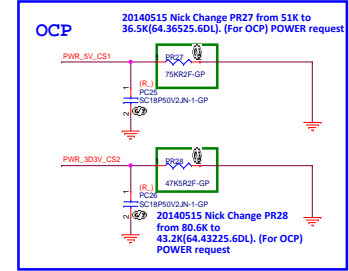
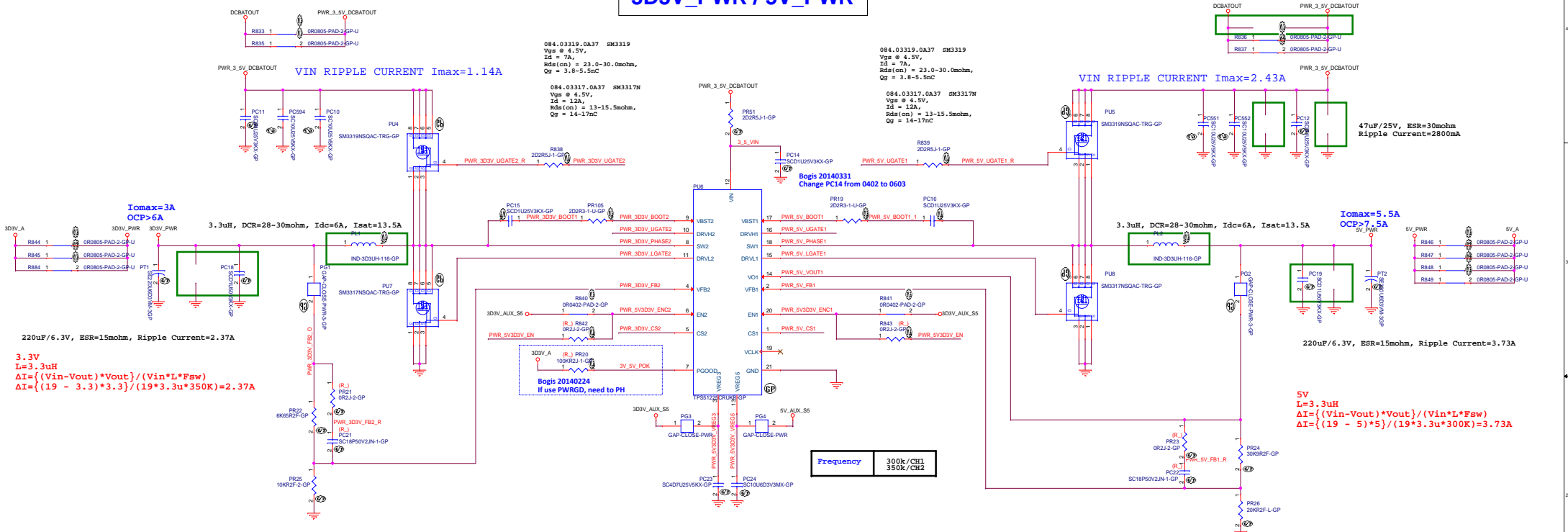
Date: Friday, September 12, 2014

Sheet 55 of 62

Rev
1A

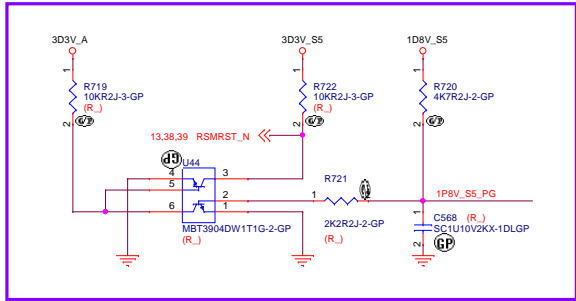


3D3V_PWR / 5V_PWR



TONSEL	CH1	CH2
GND	200kHz	250kHz
VREF	300kHz	375kHz
VRBG3 or VRBG5	400kHz	500kHz

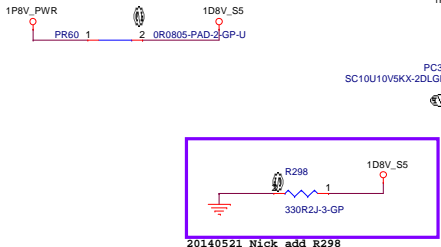
SKIPSEL	VRBG3 or VRBG5	VREF(2V)	GND
Operating Mode	OOA Auto Skip	Auto Skip	PWM only



3D3V_S5 -> 1D8V_S5

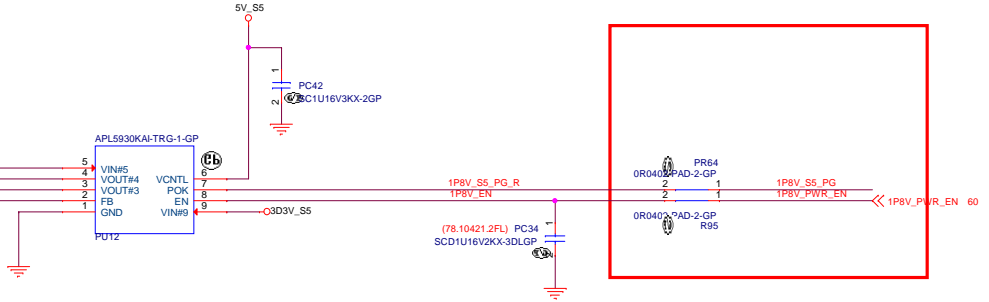
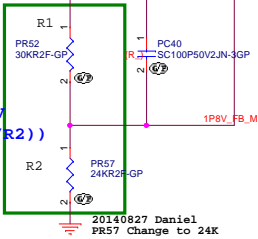
$$P_d = (3.3 - 1.8) \times 3 = 0.225W$$

1D8V_S5
I_{omax} = 0.15A



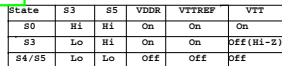
$$V_o(\text{cal.}) = 1.795V$$

$$V_o = 0.8 \times (1 + (R1/R2))$$



V_SM_VTT

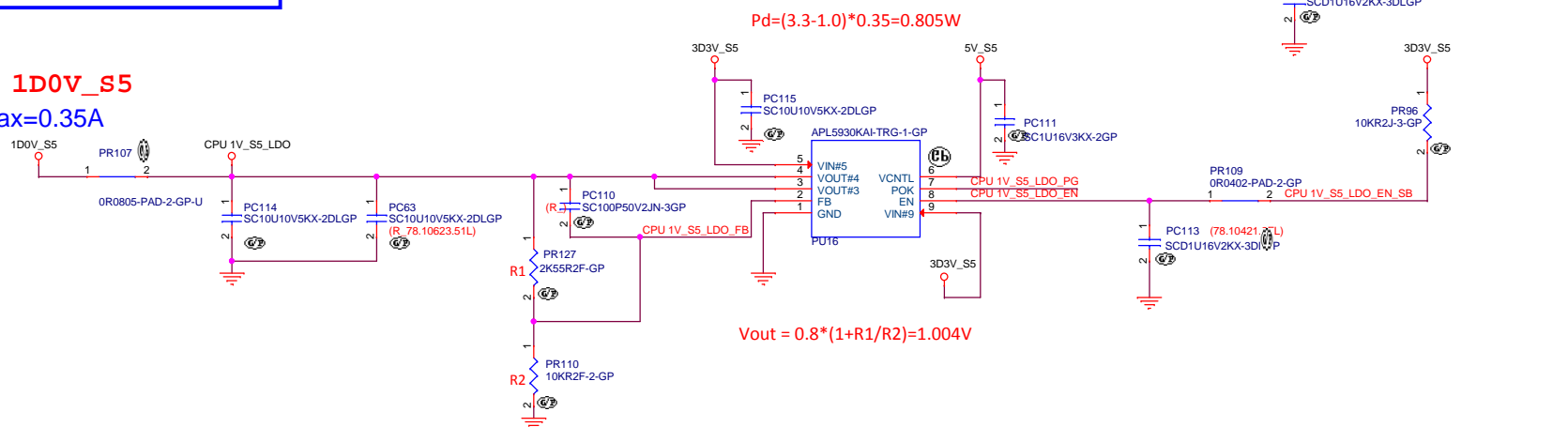
EE need check


$$I_{\max} = 0.445A$$

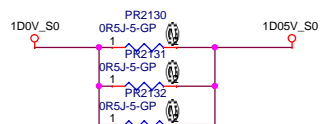

2014/4/28 Nick change from
1D05V_RUNPWROK to
+V_3P3_VGA

3D3V_S5 -> 1D0V_S5

CPU 1D0V_S5
I_{omax}=0.35A



Merger 1D05V_S0 -> 1D0V_S0



<Core Design>

wistron

Wistron Incorporated
12F, 88, Hsin Tai Wu Rd
Hsichih, Taipei

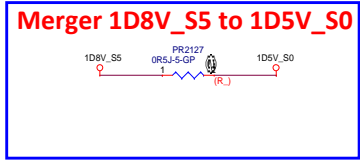
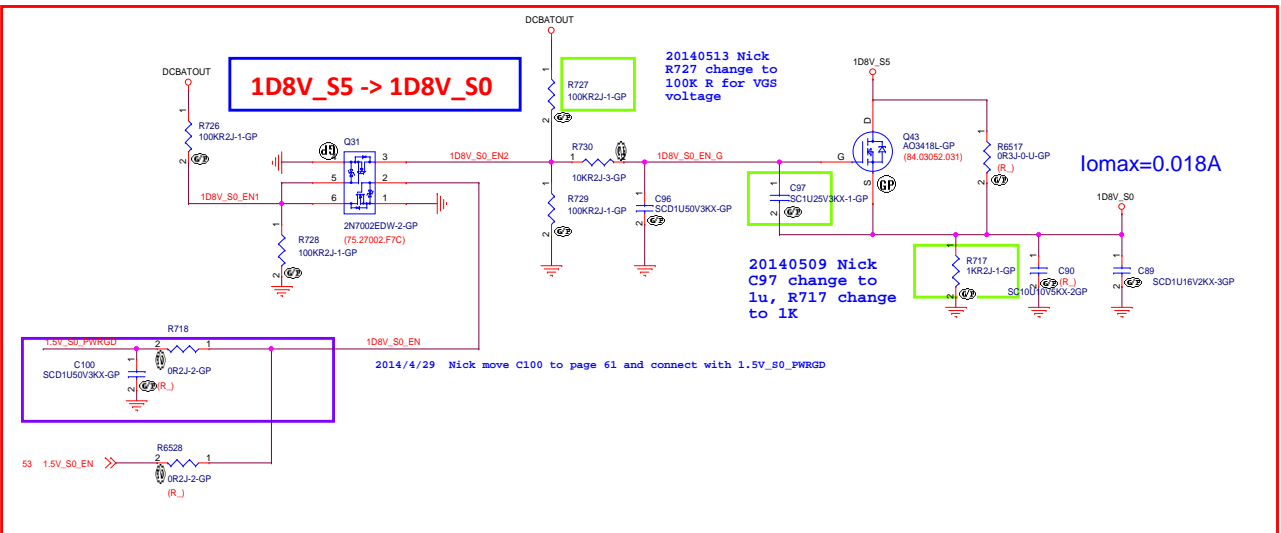
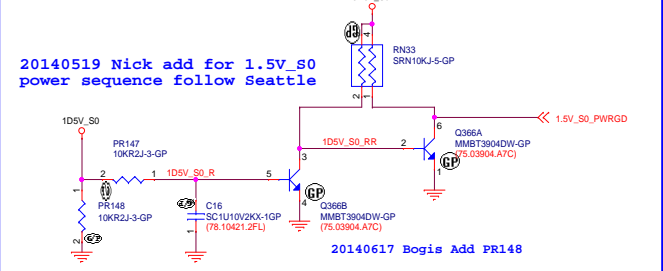
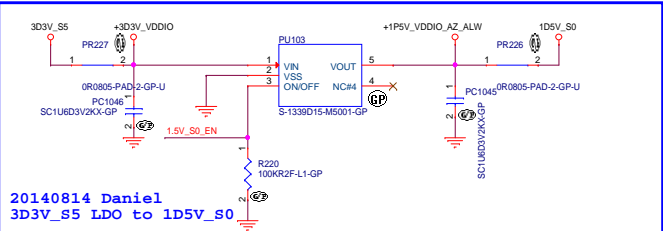
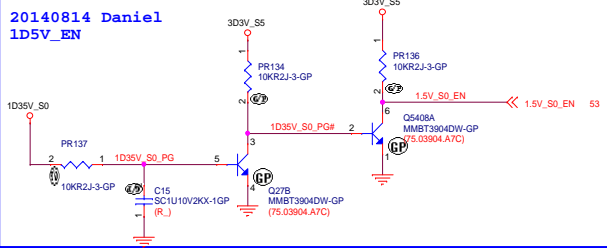
Title **PWR_CPU 1V_S0&CPU 1V_S5**

Size Custom Low Cost AIO

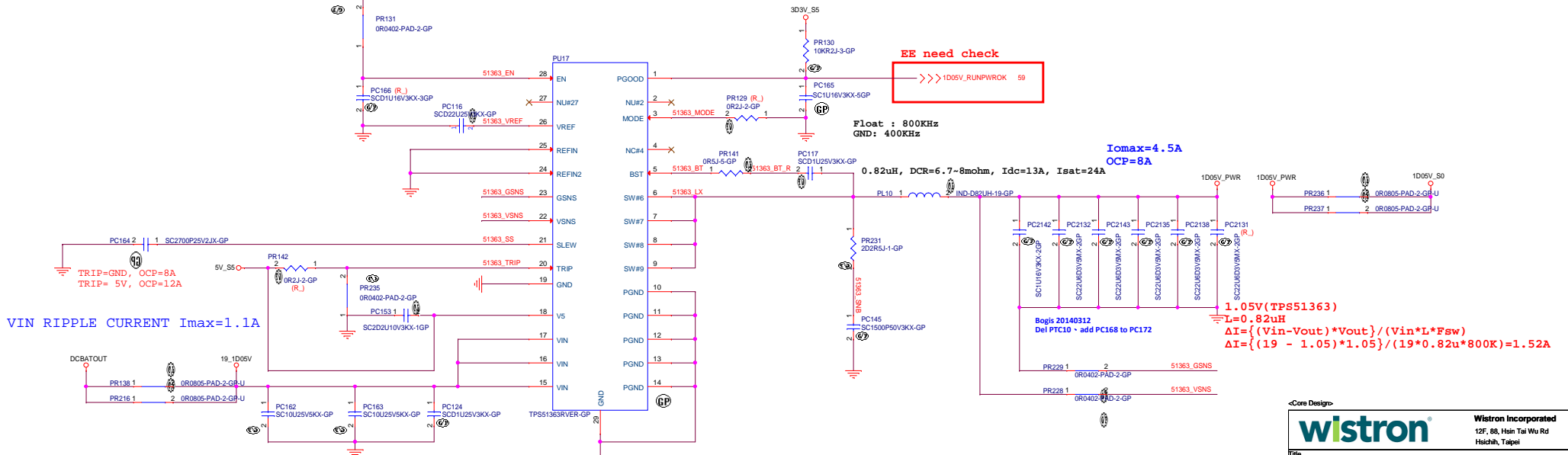
Rev 1A

Date: Friday, September 12, 2014

Sheet 60 of 62




1.05V
EE need check



Connect GSNS to output capacitor ground and VSNS to positive terminal of output capacitor, run these two trace as differential

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

<Variant Name>

		Wistron Incorporated 12F, 88, Hsin Tai Wu Rd Hsichih, Taipei	
Title PWR_12V			
Size	Document Number		Rev
Custom	Low Cost AIO		1A
Date:	Friday, September 12, 2014	Sheet 62 of 62	